

Session 6 - Power Management Circuits and Architectures

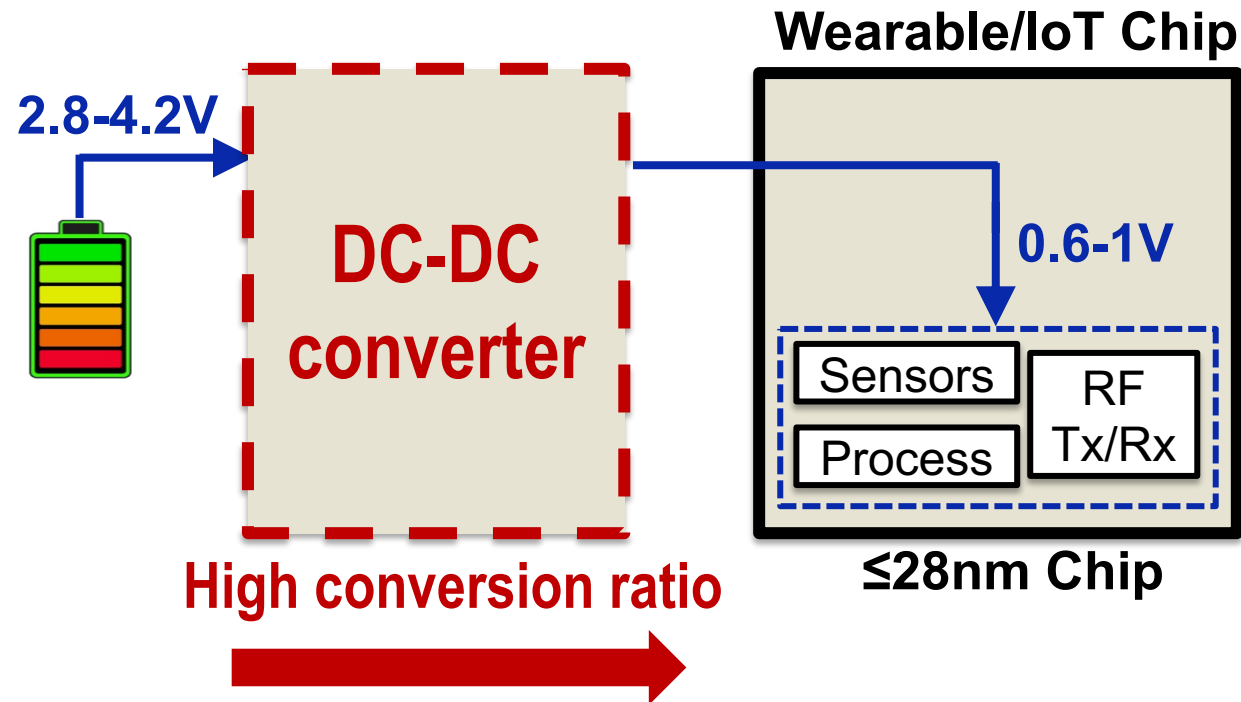
A 78%-Efficiency Li-ion-Compatible Fully-Integrated Modified 4-Level Converter with 0.01- 40mW DCM-Operation in 28nm FDSOI

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UC San Diego

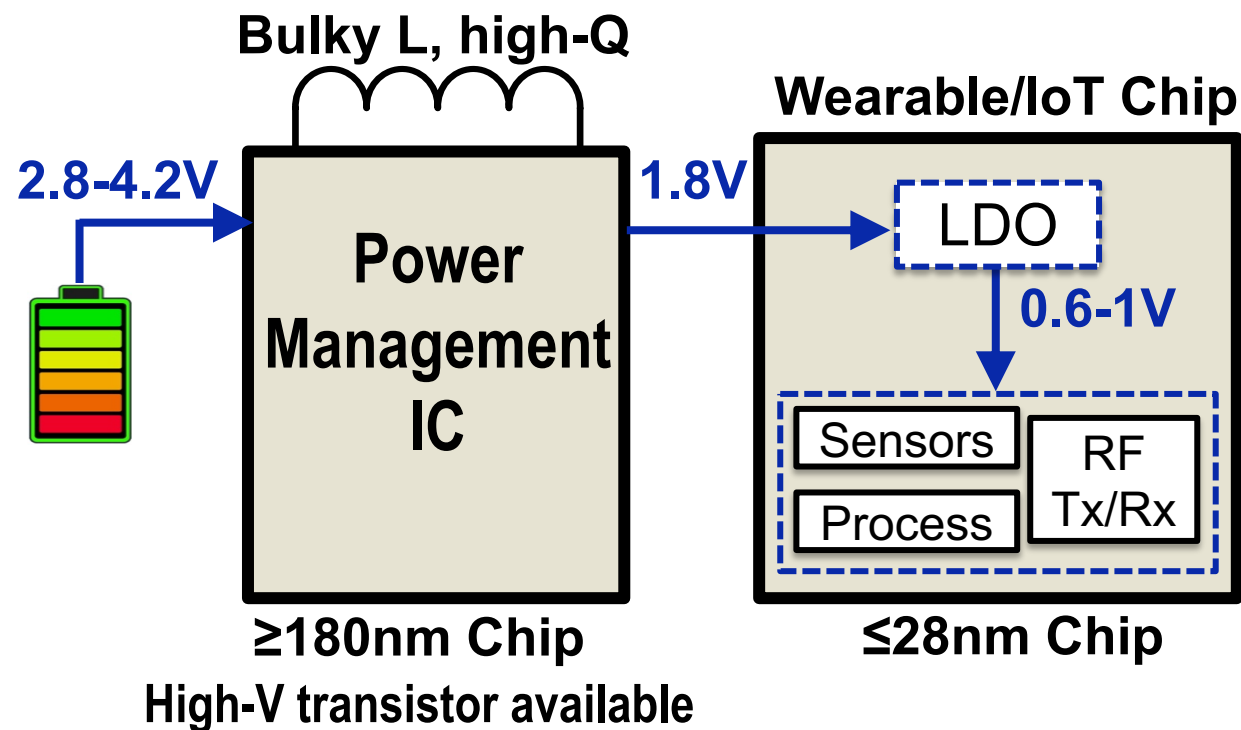
Powering IoT and Wearables in Scaled-CMOS



Small wearable/IoT devices is implemented in scaled-CMOS and use Li-ion batteries as power supply

Powering IoT and Wearables in Scaled-CMOS

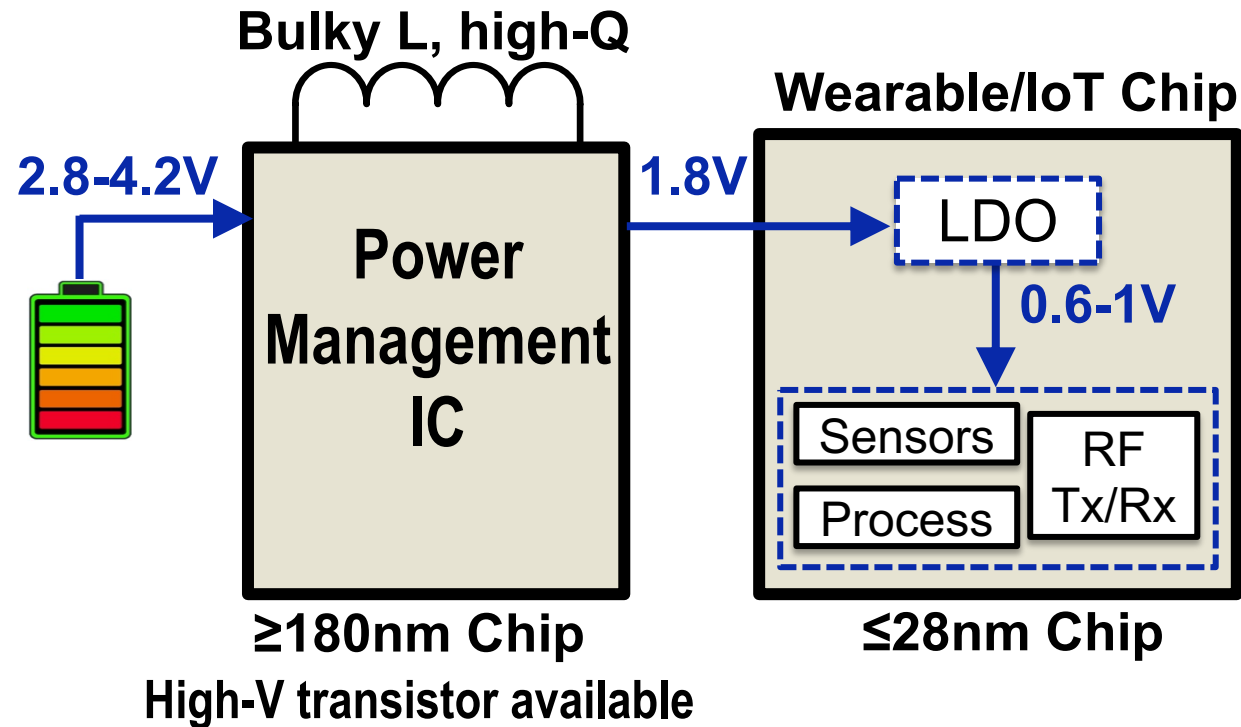
Conventional



Discrete PMIC is implemented in technologies that can handle the high battery voltage

Powering IoT and Wearables in Scaled-CMOS

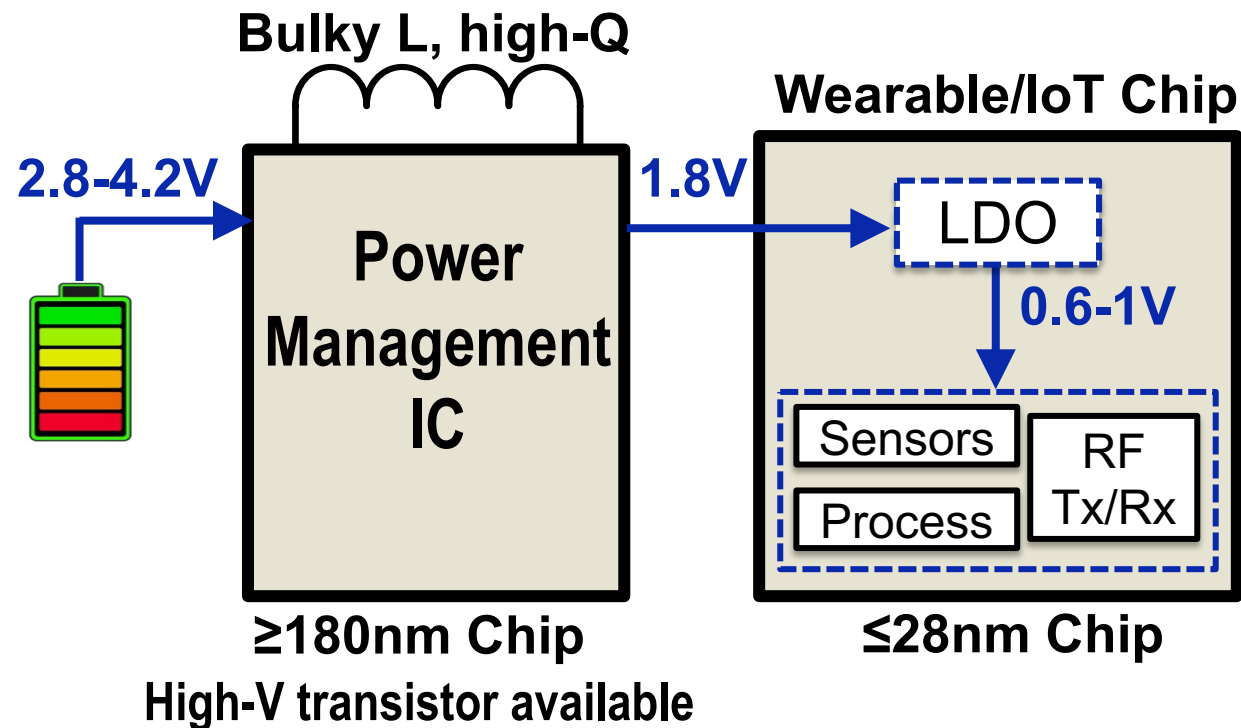
Conventional



↑ Area ↑ PCB complexity/cost

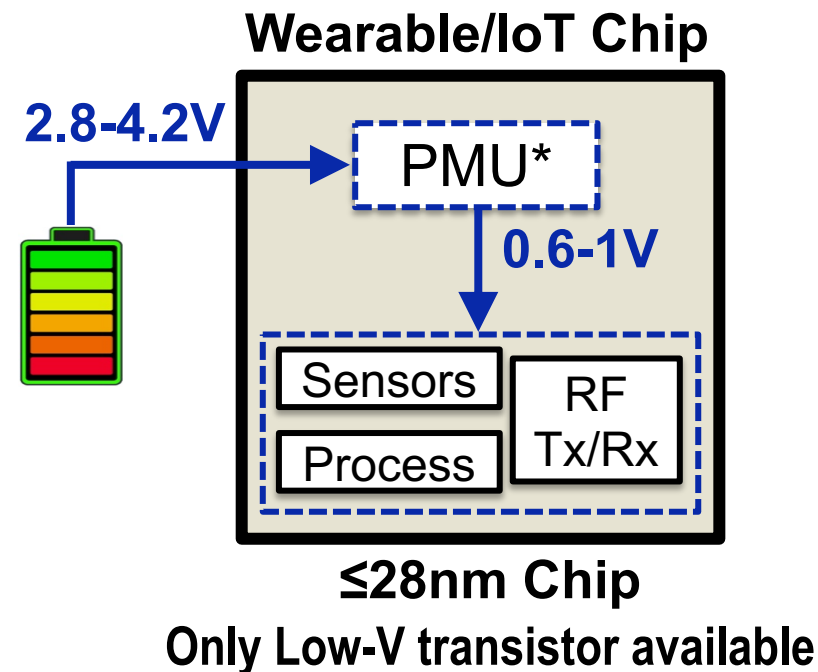
Powering IoT and Wearables in Scaled-CMOS

Conventional



↑ Area ↑ PCB complexity/cost

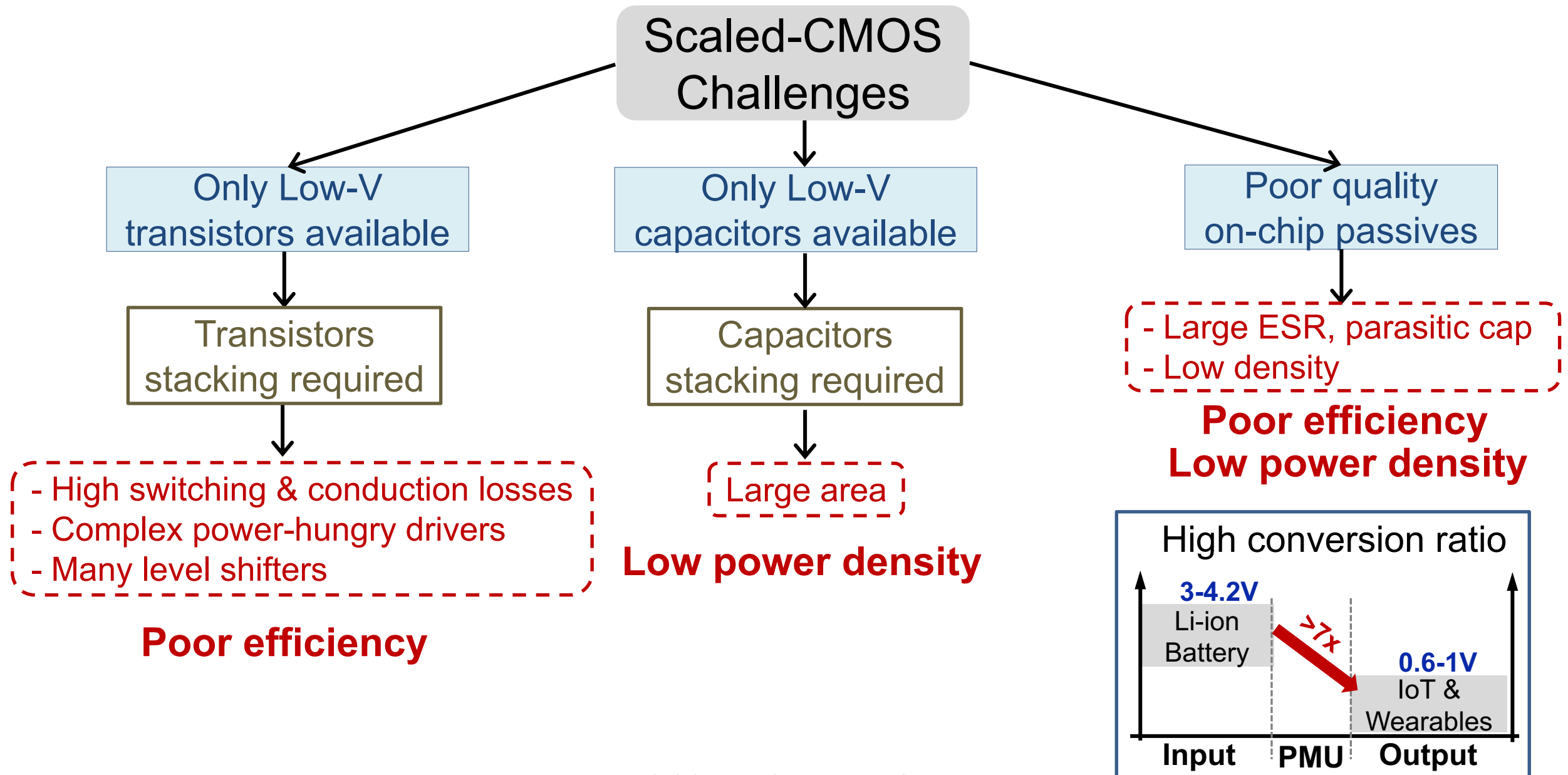
Goal



Small form factor
↓ PCB complexity/cost

PMU* : Power Management Unit

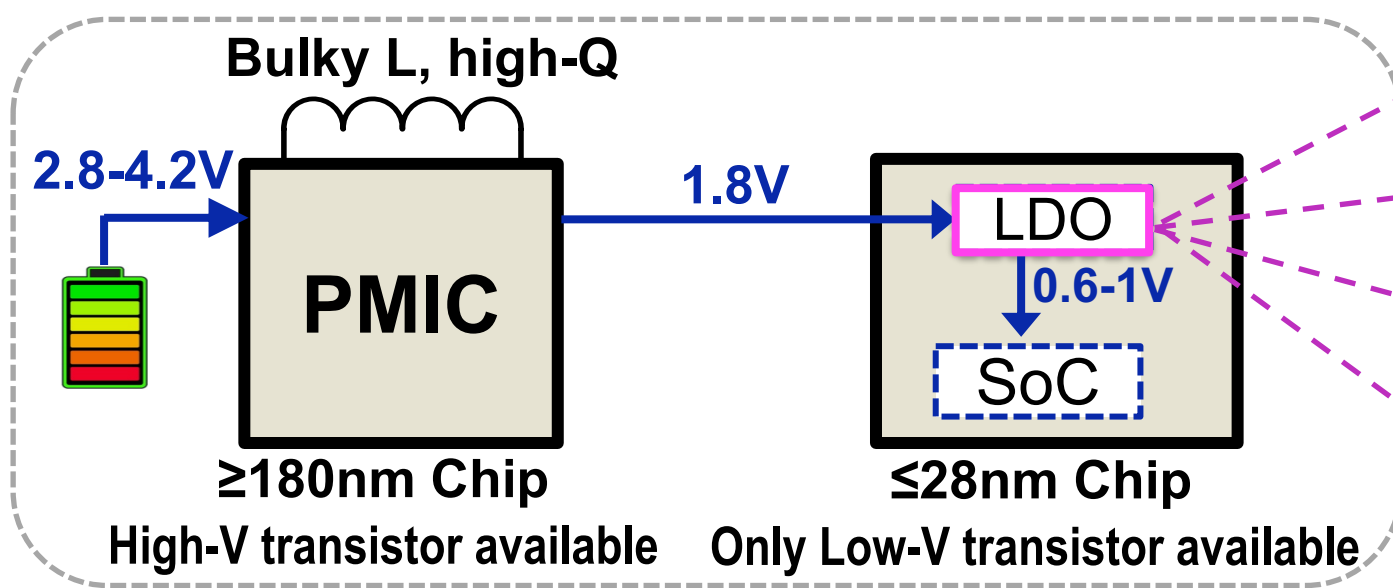
Li-ion Fully-Integrated PMU Challenges in 28nm FDSOI



Outline

- **Prior Work**
- Proposed Hybrid Architecture
- Switching Phases of the Proposed Architecture
- Circuit Details
- Measurement Results
- Conclusion

Prior Work

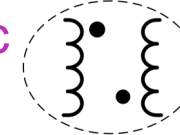


Buck



Krishnamurthy et al., VLSI'14

Magnetic coupling



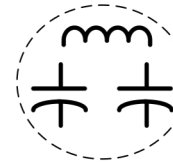
Lee et al., ITIA'16
Wibben et al., JSSC'08

SC

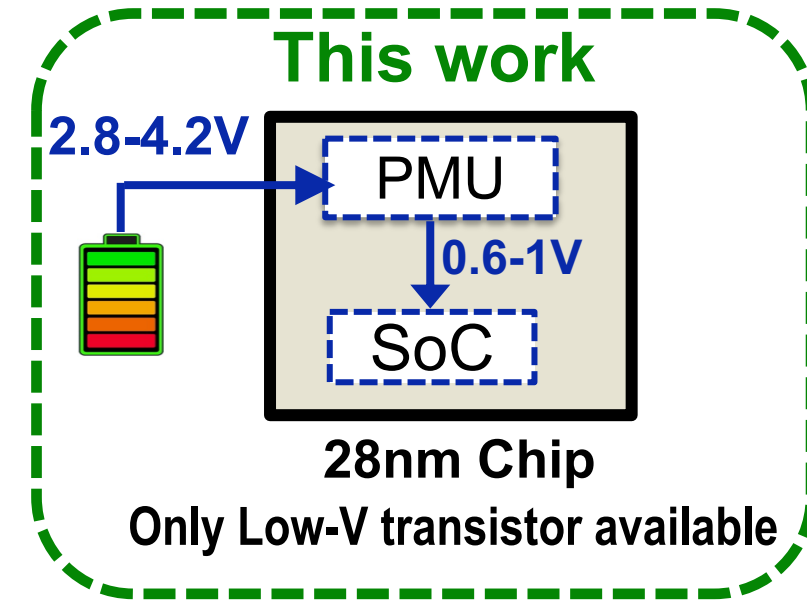
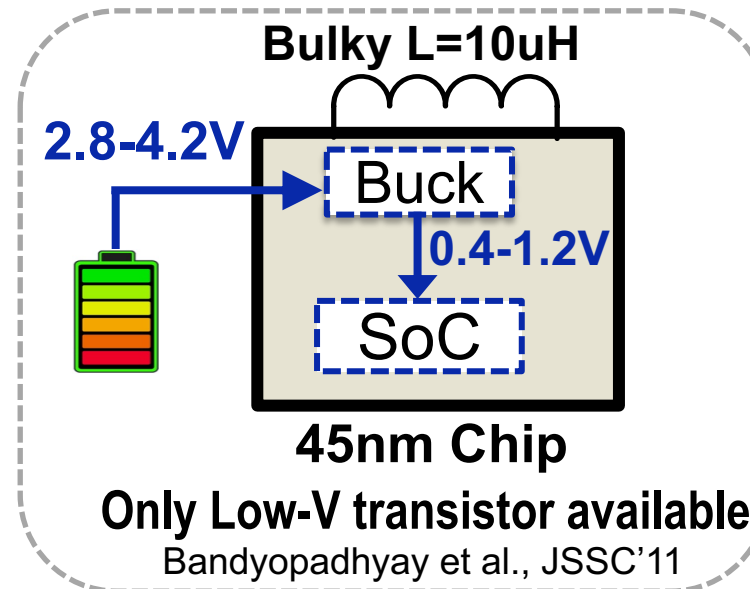
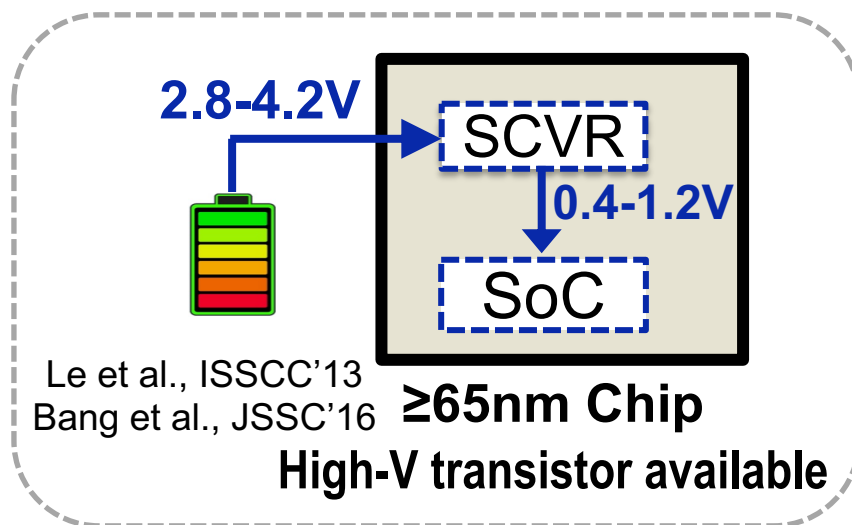


Souvignat et al., TPEL'16

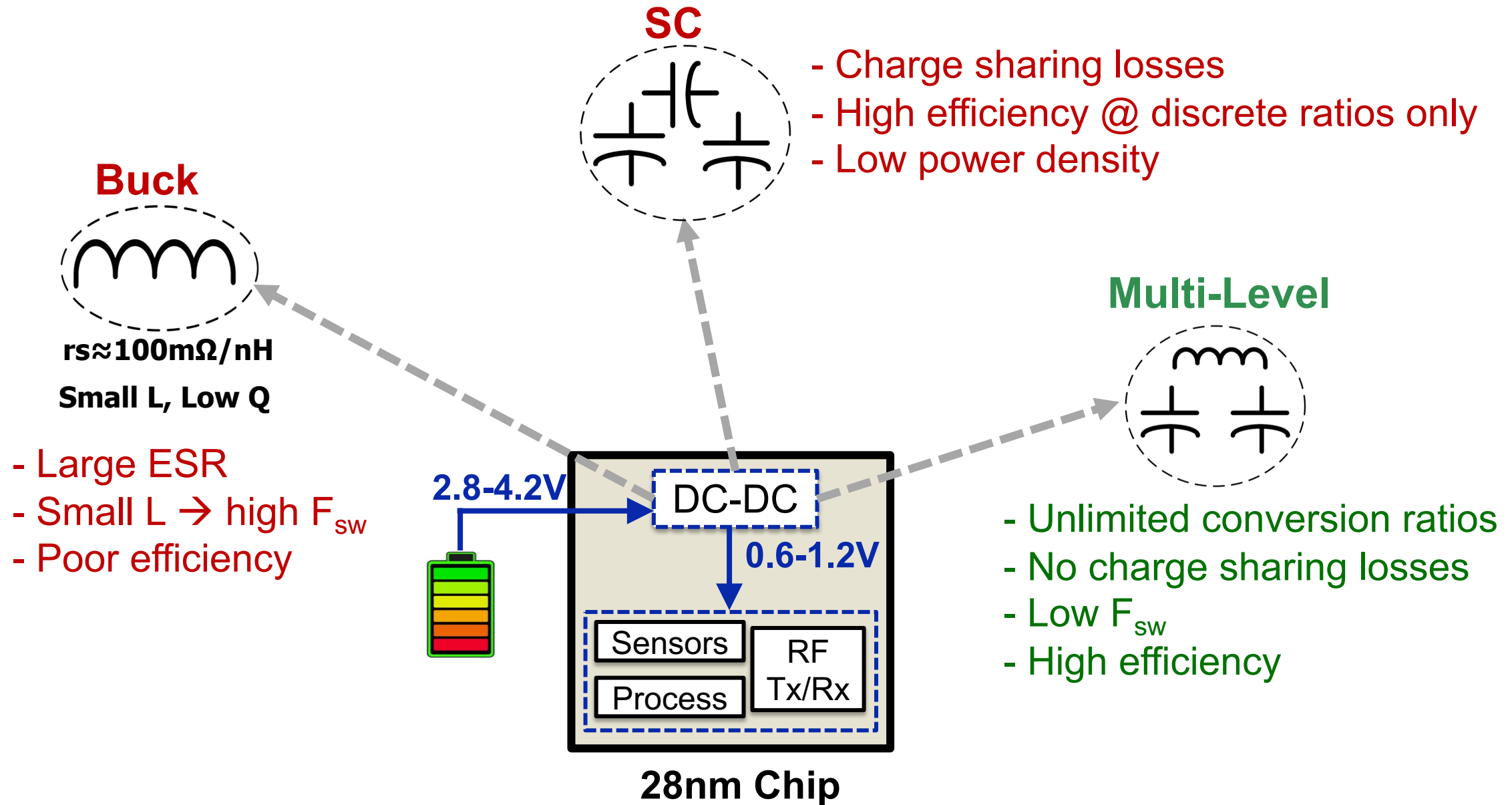
3-Level



Kumar et al., CICC'15



Fully Integrated DC-DC Converter for $V_{in}=2.8-4.2V$



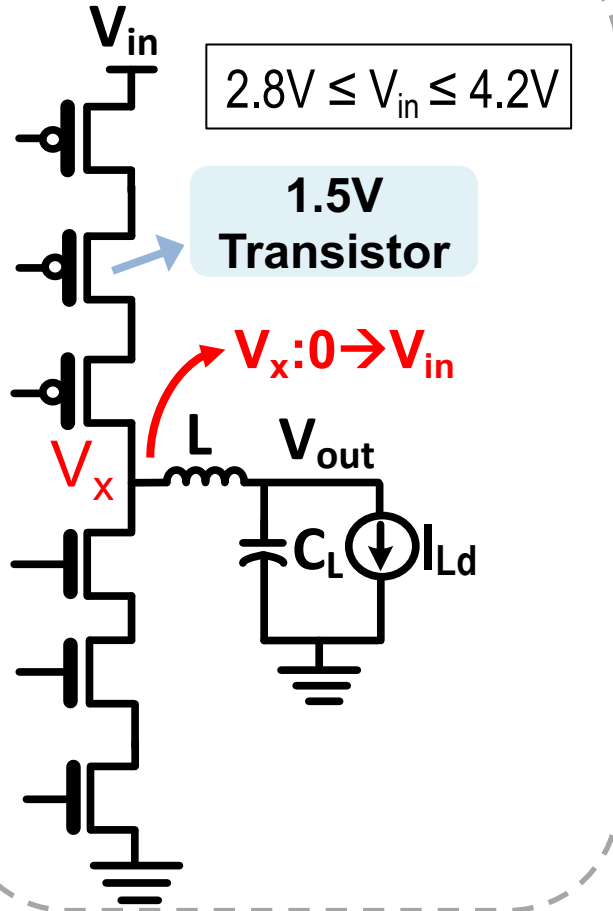
Outline

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Towards Fully-Integrated Li-ion PMU in Scaled CMOS

Starting point: Buck

2-Level Buck



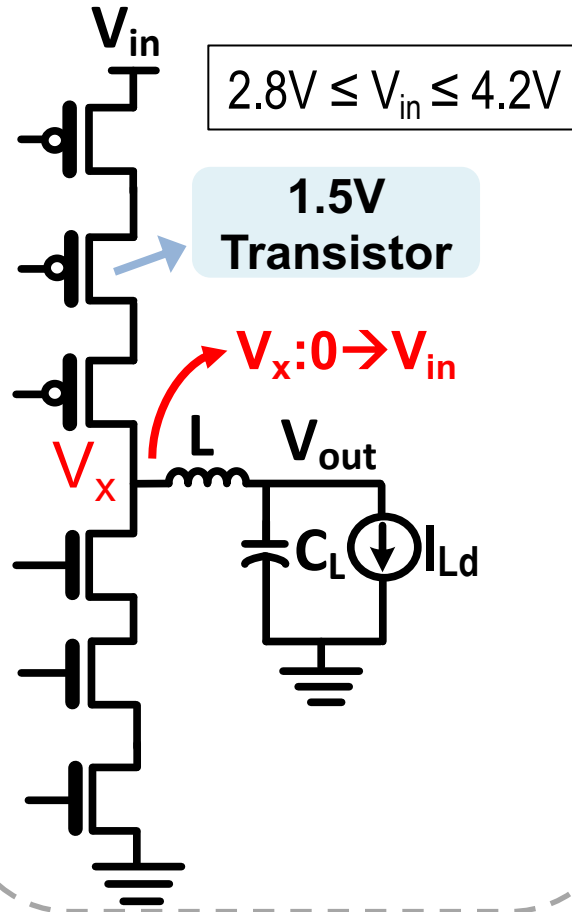
Small on-chip L , large ESR

- High Switching & conduction losses
- Poor efficiency

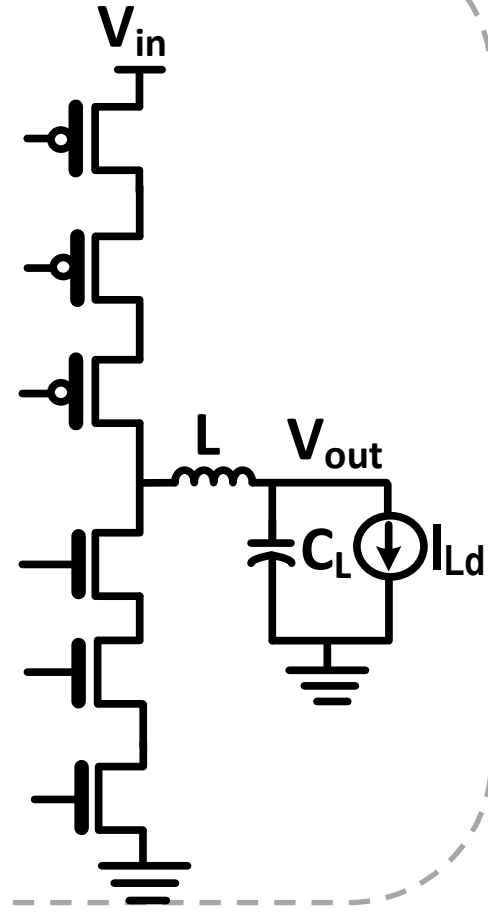
Towards Fully-Integrated Li-ion PMU in Scaled CMOS

Starting point: Buck

2-Level Buck



Improving on-chip efficiency



Stacking transistors is required anyway

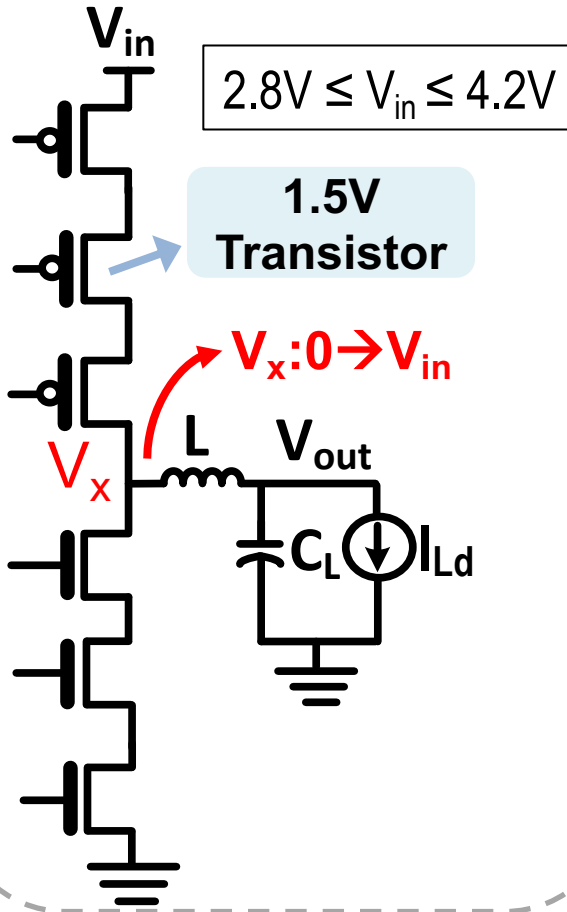
Small on-chip L , large ESR

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Towards Fully-Integrated Li-ion PMU in Scaled CMOS

Starting point: Buck

2-Level Buck

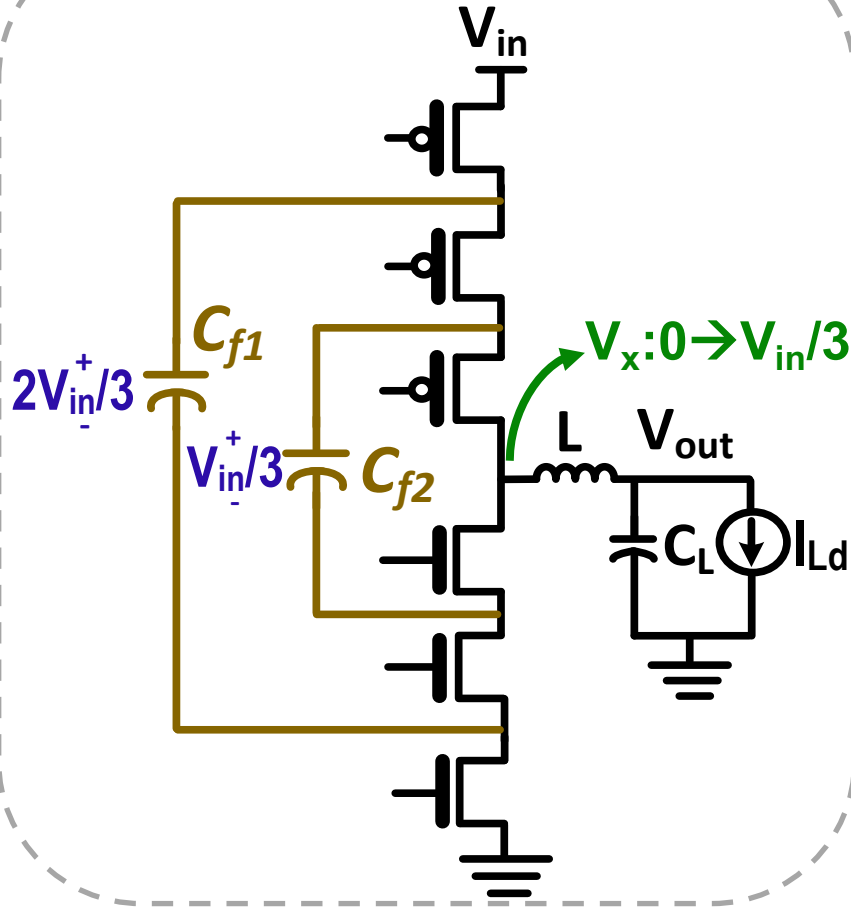


Small on-chip L , large ESR

- High Switching & conduction losses
- Poor efficiency

Improving on-chip efficiency

4-Level Converter



Reduced swing at V_x

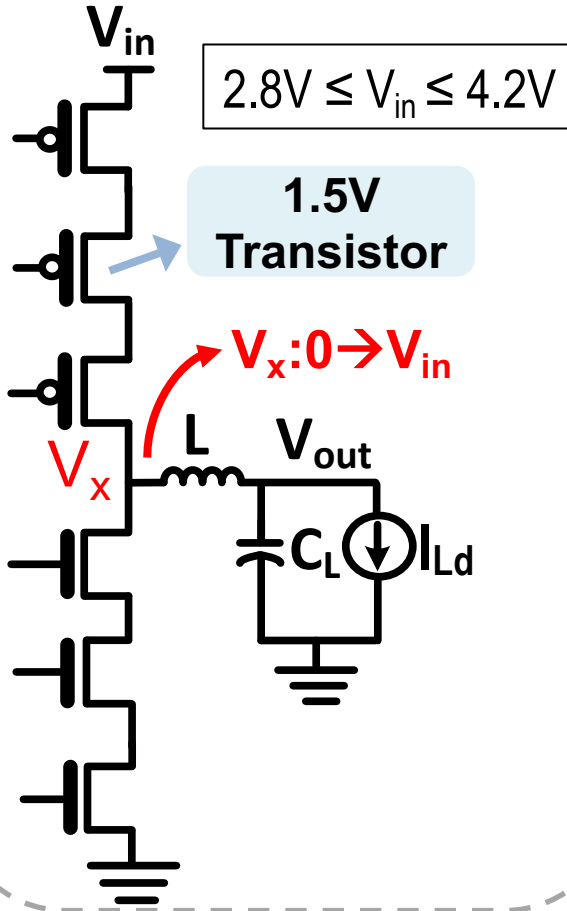
F_{sw} reduced by $> 23\times$
& efficiency by up to 33%

Stacking transistors is required anyway

Towards Fully-Integrated Li-ion PMU in Scaled CMOS

Starting point: Buck

2-Level Buck

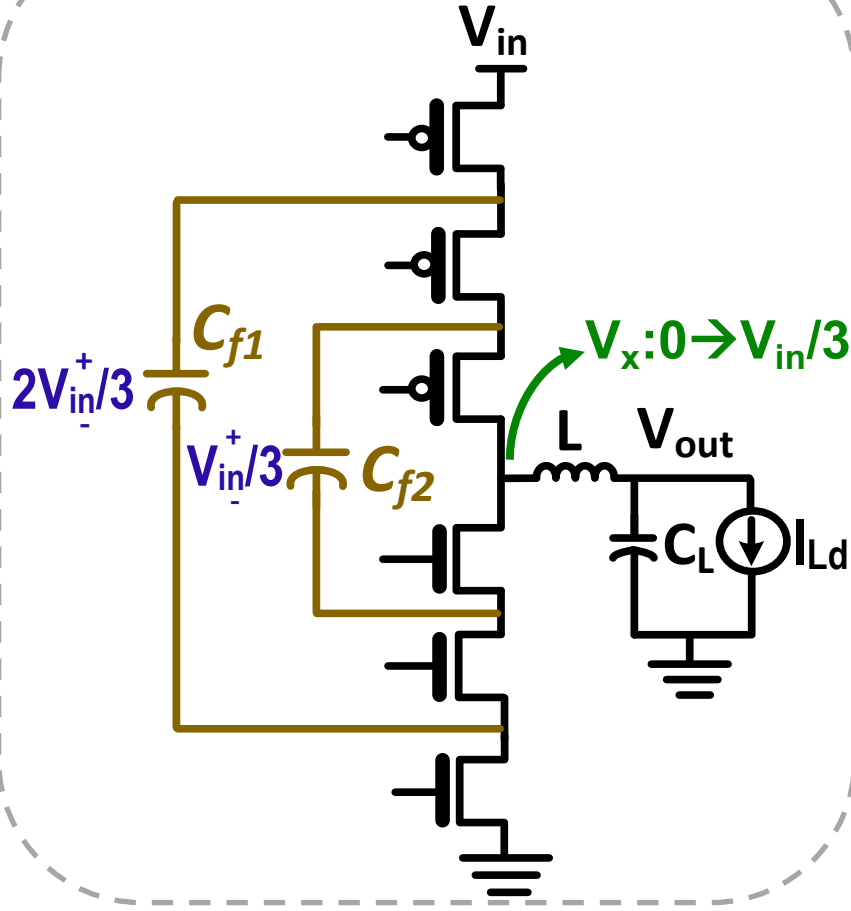


Small on-chip L , large ESR

- High Switching & conduction losses
- Poor efficiency

Improving on-chip efficiency

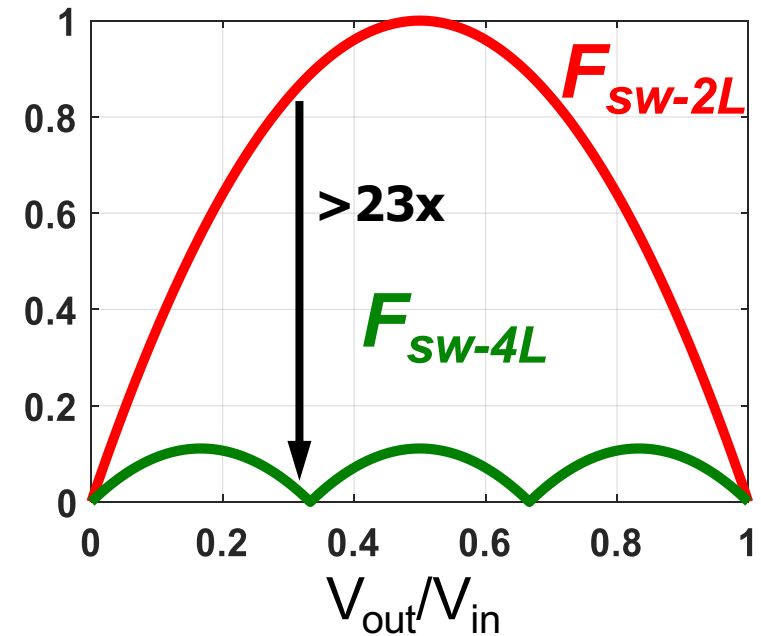
4-Level Converter



Reduced swing at V_x

F_{sw} reduced by $> 23x$
& efficiency by up to 33%

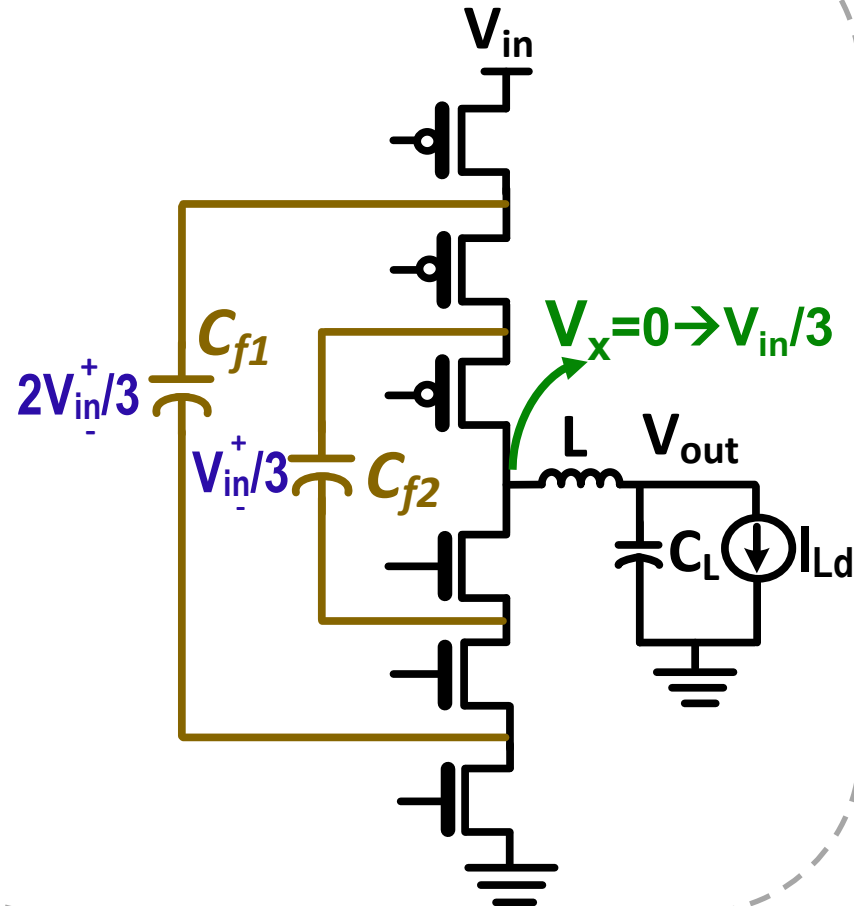
DCM-operated
Constant I_{pk}
Normalized Switching Frequency



$$\frac{F_{sw-4L}}{F_{sw-2L}} = \frac{1/3 - V_{out}/V_{in}}{1 - V_{out}/V_{in}}$$

4-Level Converter Modes of Operation

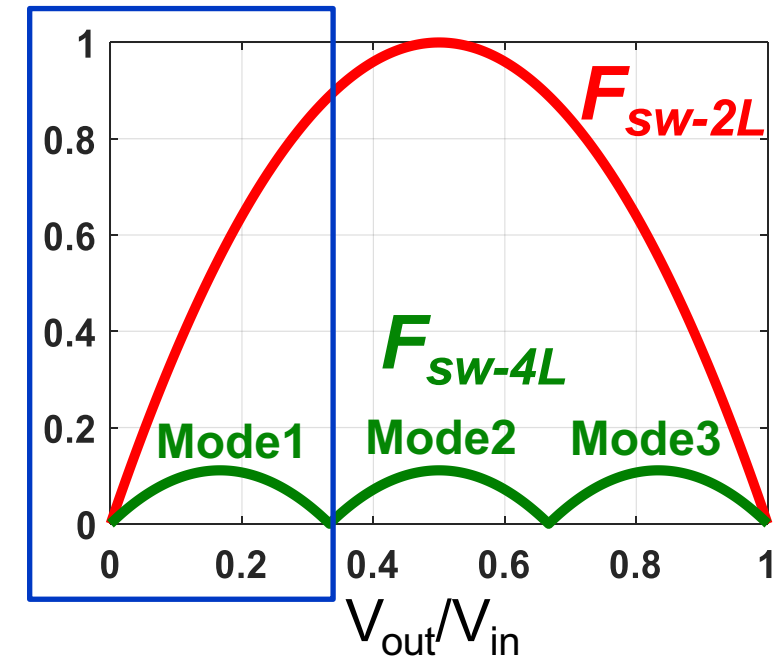
Conventional 4-Level



$$0 \leq V_{out} \leq V_{in}/3$$

The converter operates only in a single-mode for:
 $2.8 \leq V_{in} \leq 4.2$ & $0.6 \leq V_{out} \leq 1$

Constant I_{pk}
 Normalized Switching Frequency



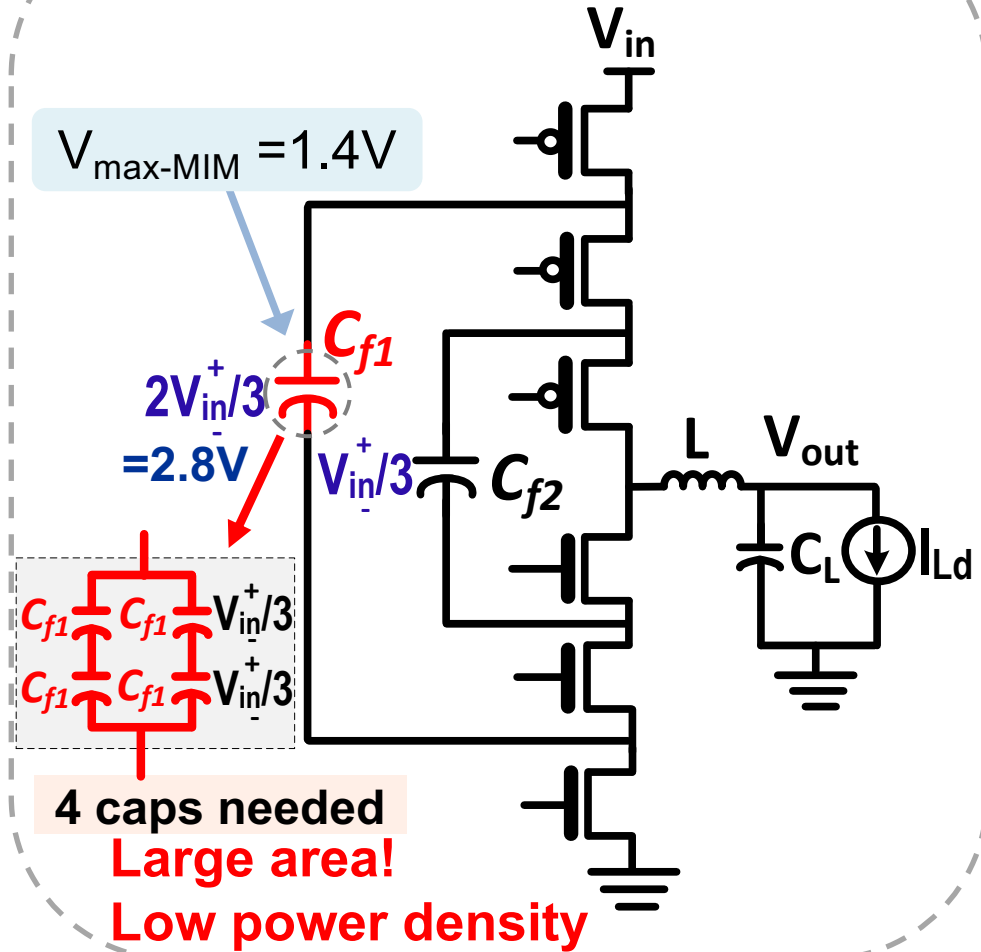
Mode1: $V_x = 0 \rightarrow V_{in}/3$

Mode2: $V_x = V_{in}/3 \rightarrow 2V_{in}/3$

Mode3: $V_x = 2V_{in}/3 \rightarrow V_{in}$

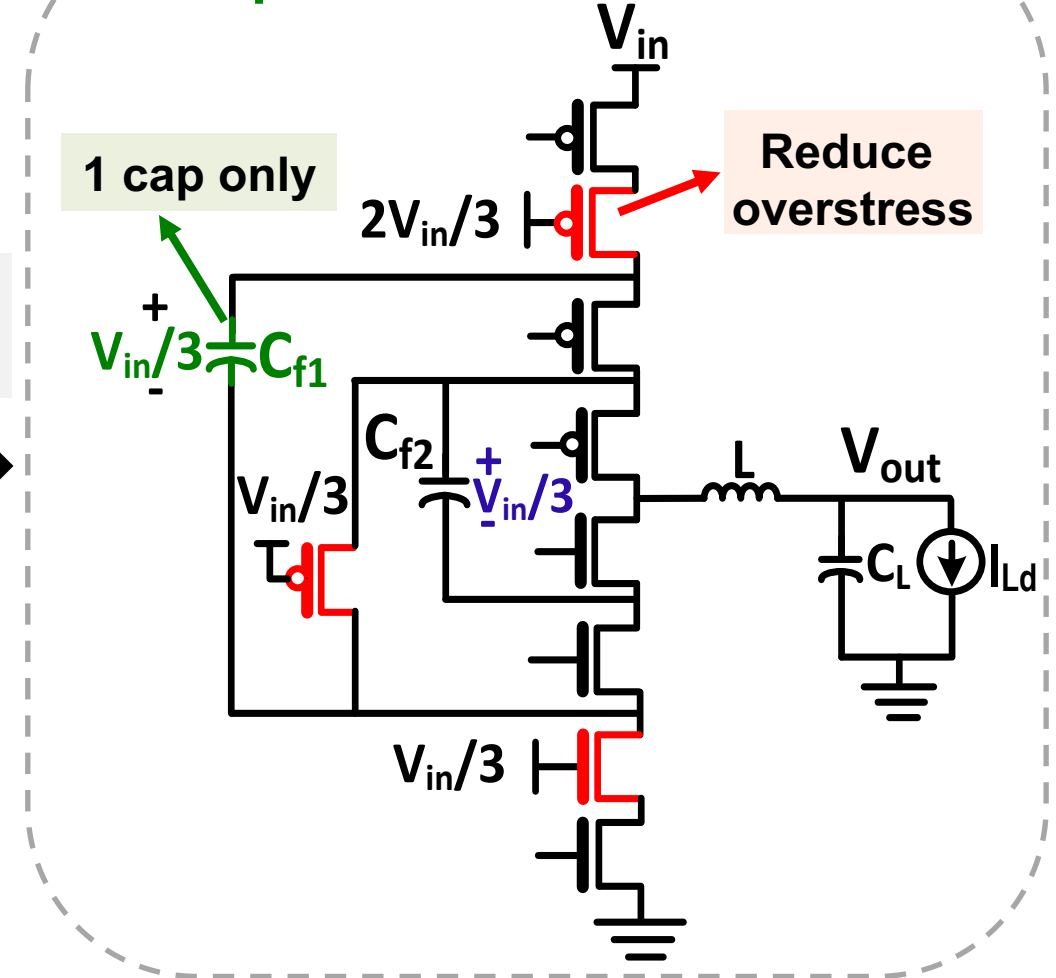
Conventional 4-Level Converter Area Penalty

Conventional 4-Level



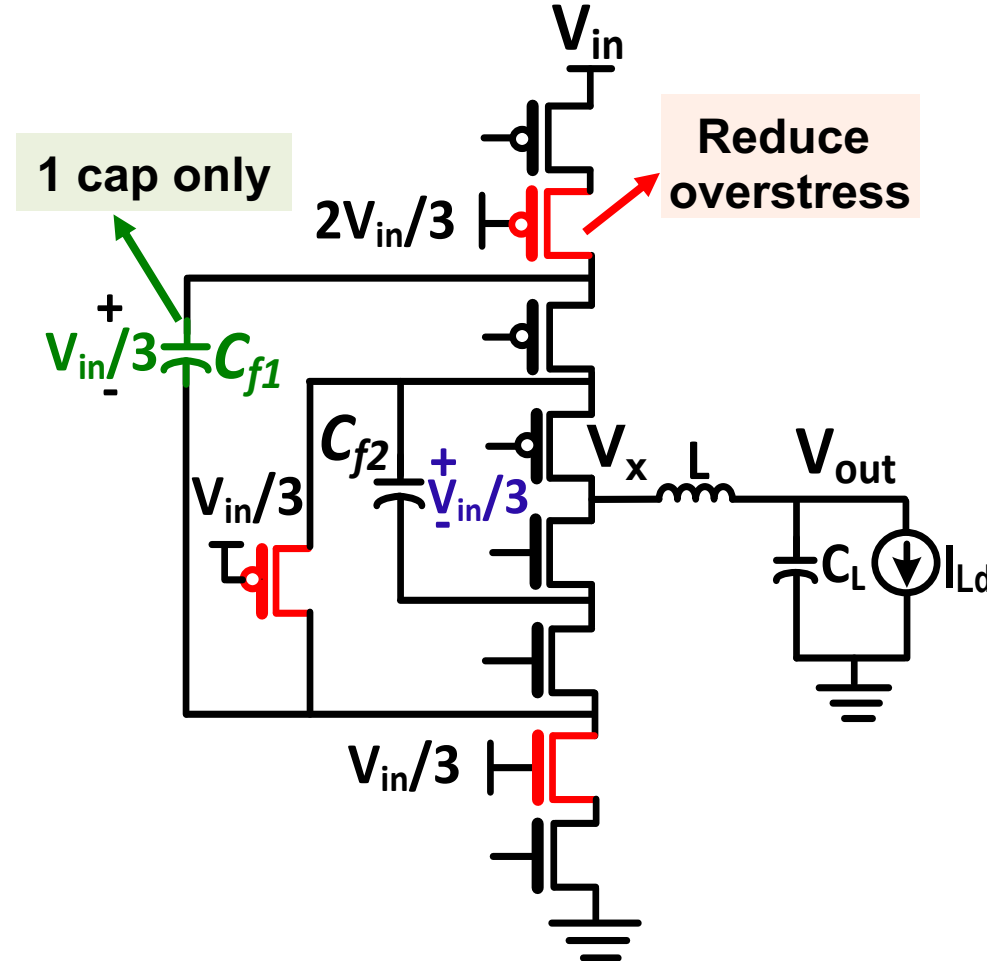
Reducing cap area by 4x

Proposed Modified 4-Level



Changing the switching states of flying caps reduces the cap voltage stress

Proposed Modified 4-Level Converter

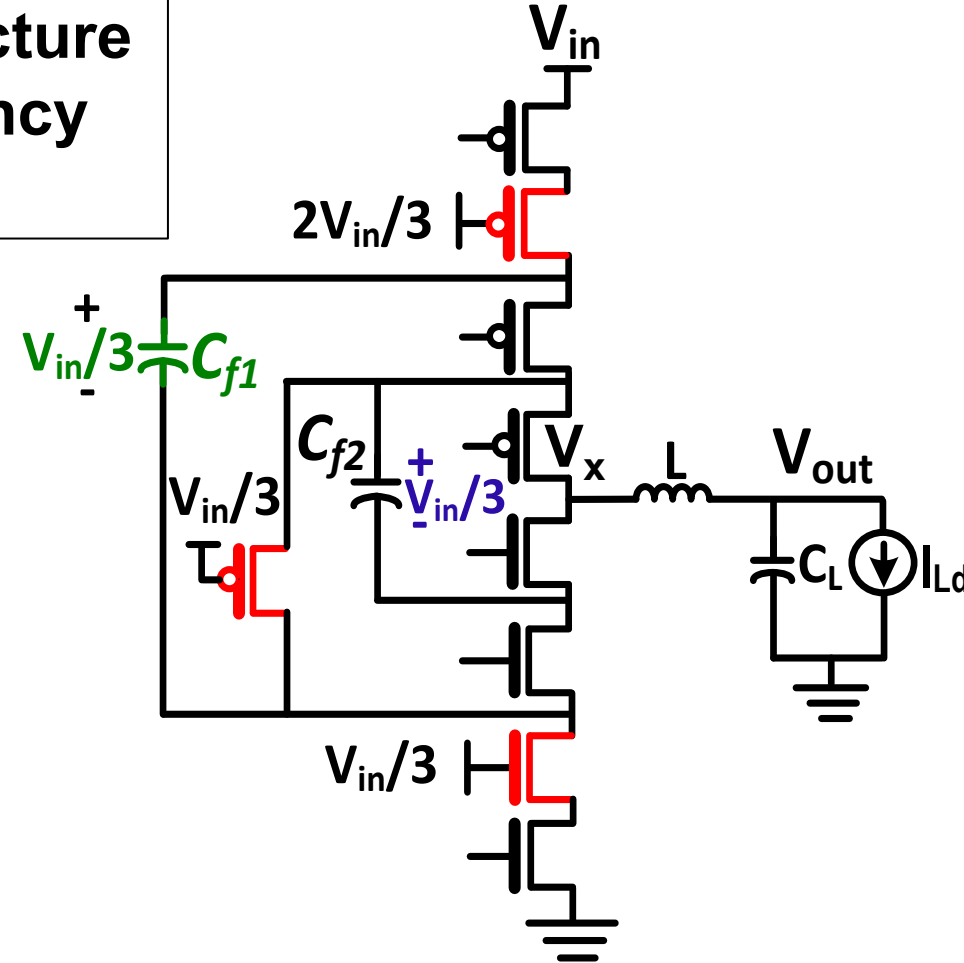


For same area, this topology can offer up to 12% higher efficiency

The overall efficiency is higher even with the added power switches because the proposed architecture allows larger passives for same area

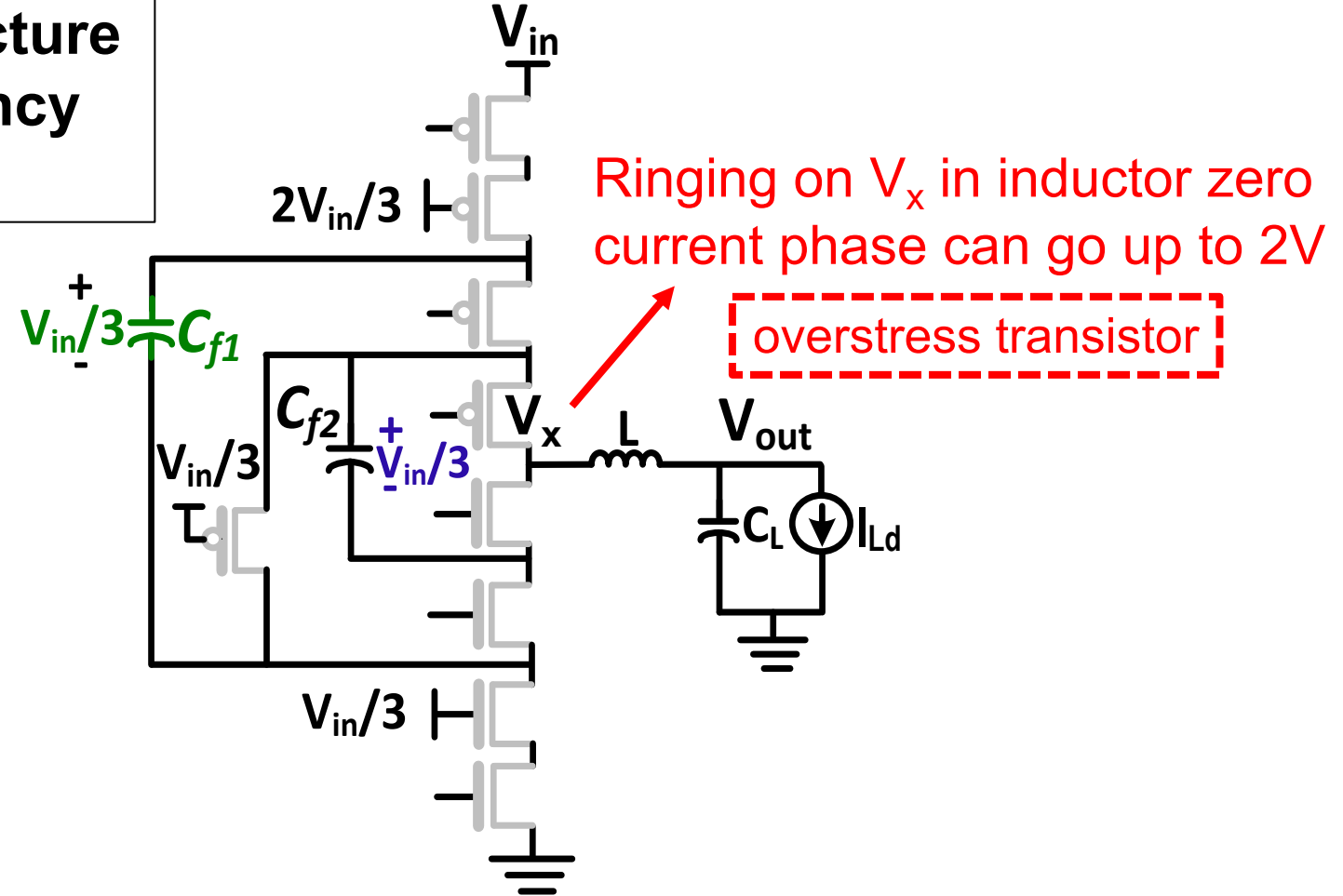
DCM-Operated Modified 4-Level Converter

DCM-operated architecture
to achieve high efficiency
@ low load current



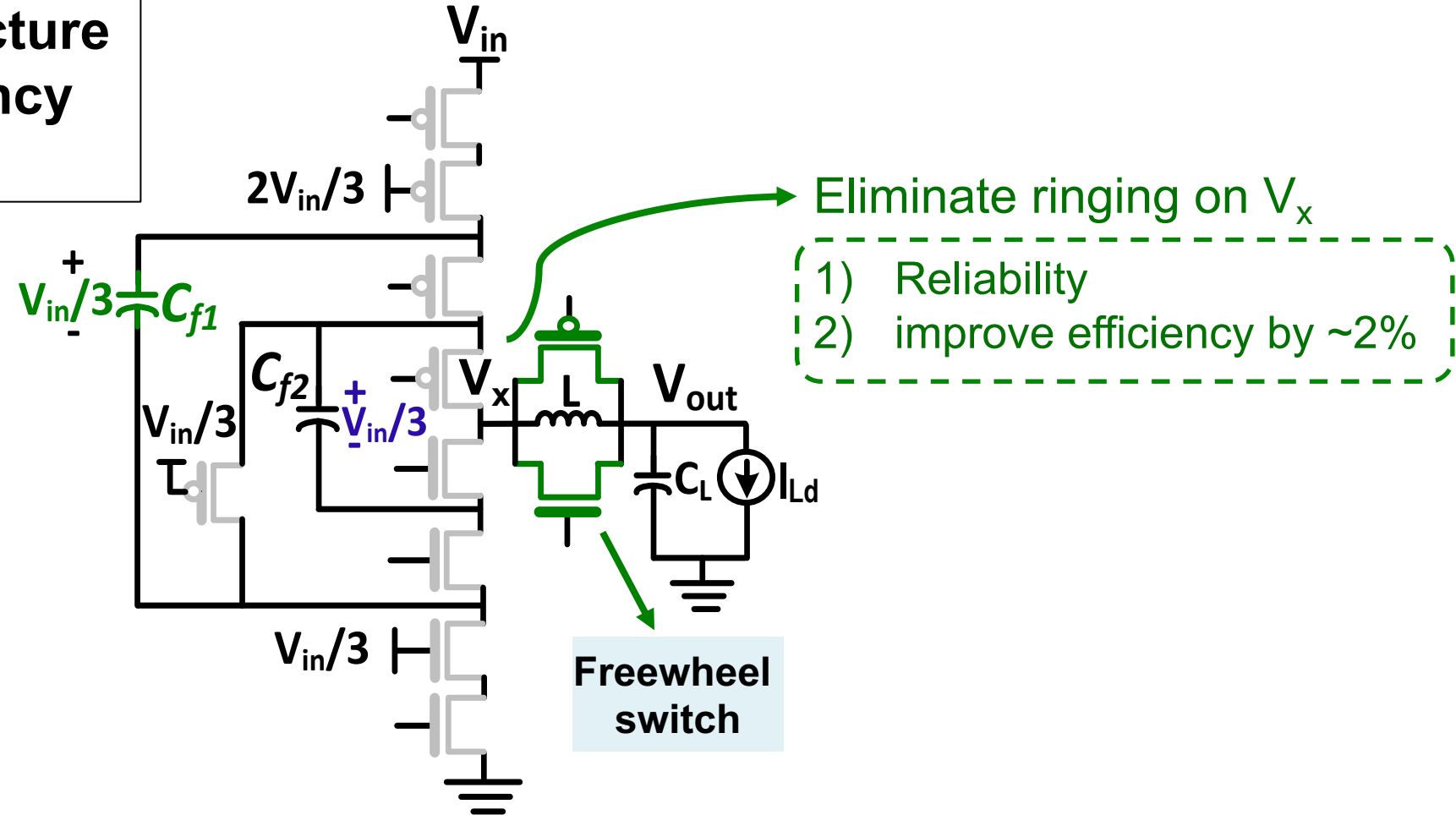
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DCM-Operated Modified 4-Level Converter

DCM-operated architecture
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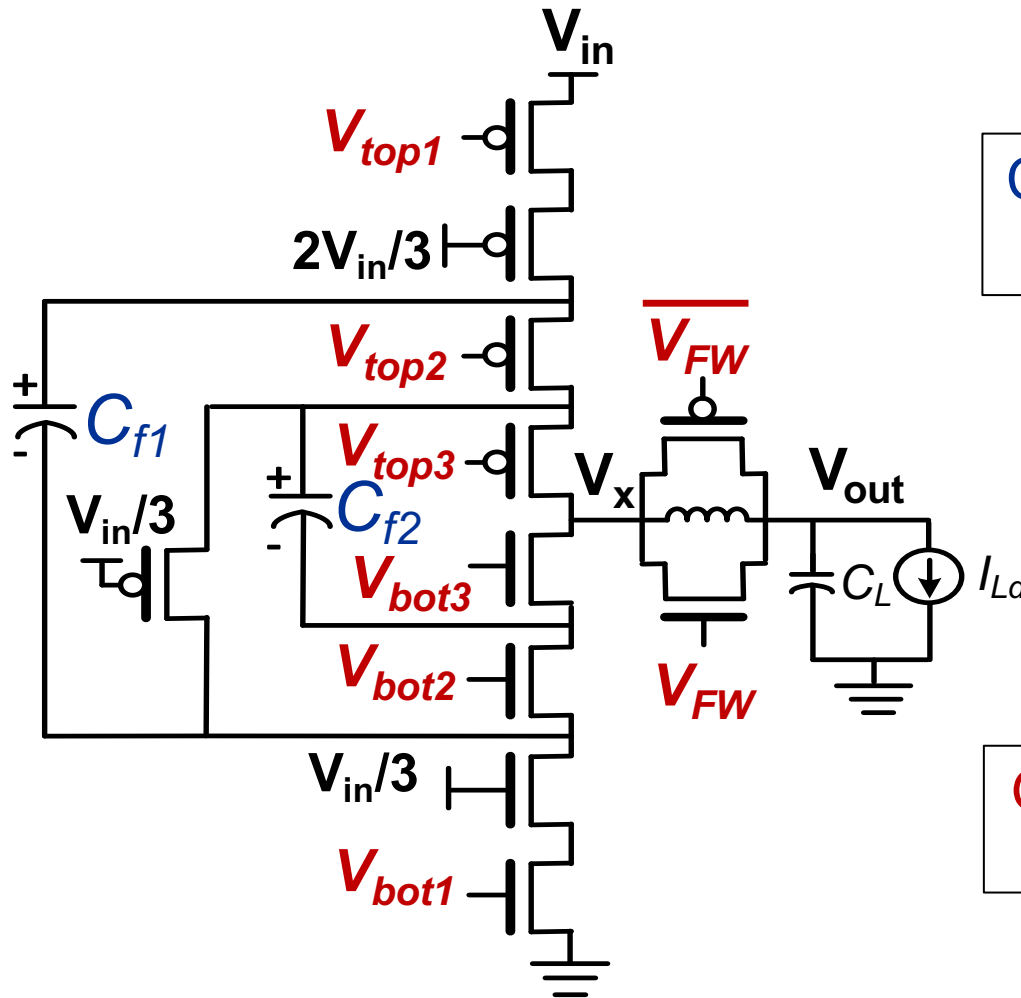
FW switches don't contribute to losses:

- 1) Turn ON only in zero current phase (~no conduction losses)
- 2) Sized much less than other FETs

Outline

- Prior Work
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- **Switching Phases of the Proposed Architecture**
- Circuit details
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Converter Switching Cycle: 7 Inductor Phases



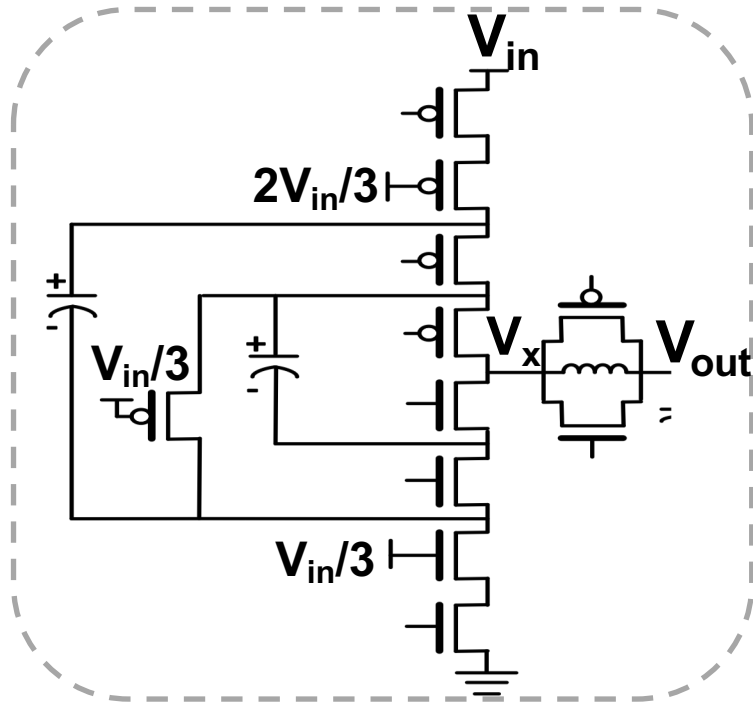
Capacitors steady state voltage:

$$V_{f1} = V_{f2} = V_{in}/3$$

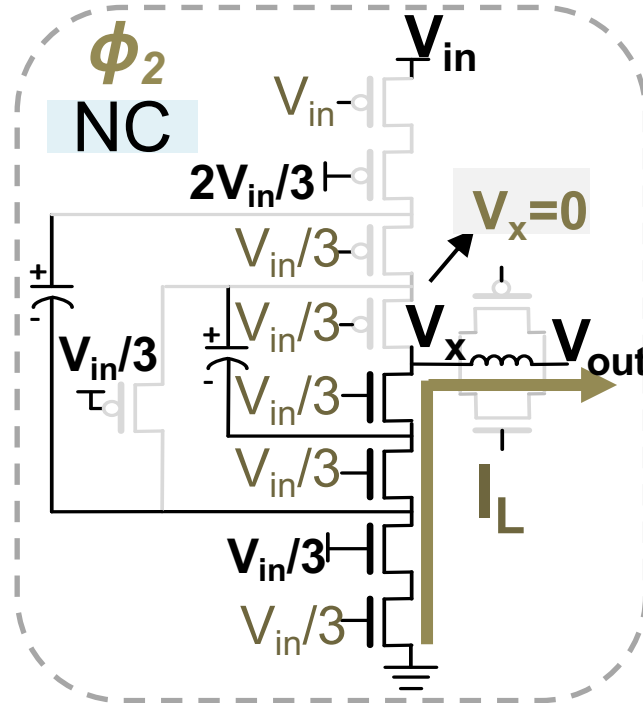
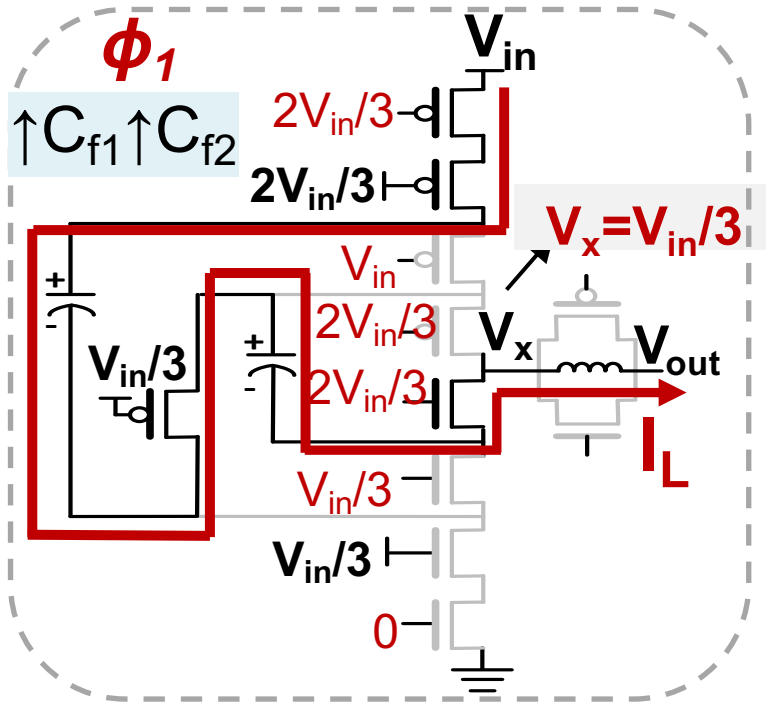
Gate signals in each phase set such that no transistor exceeds $V_{in}/3$

There are 7 different inductor switching phases in one converter switching cycle

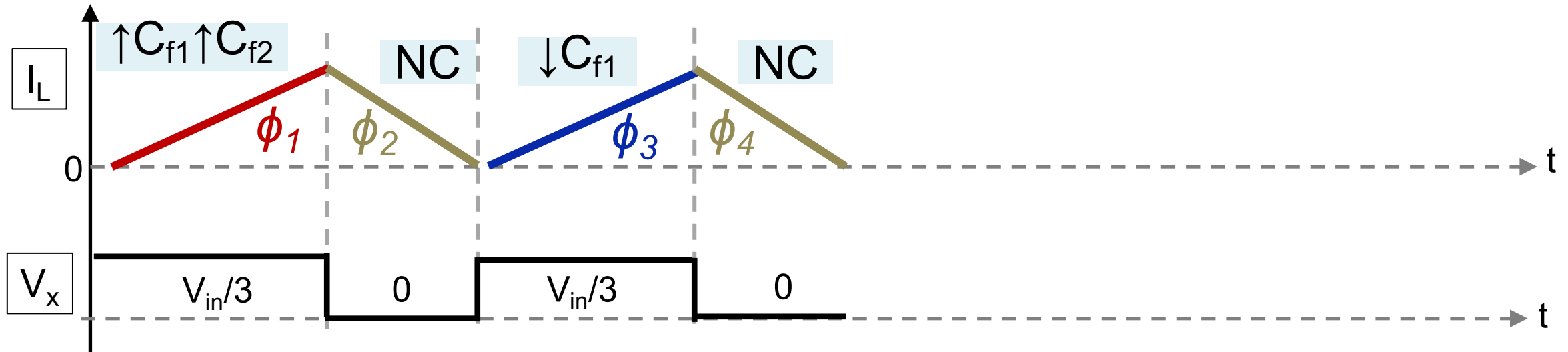
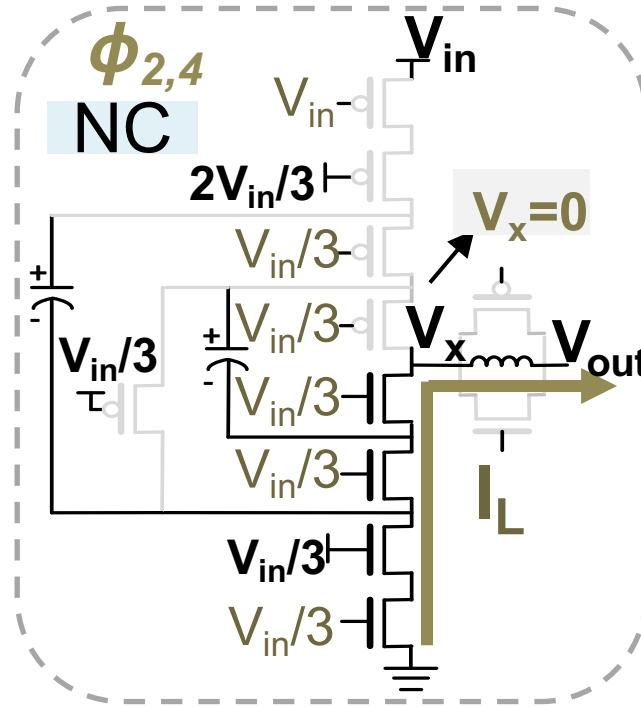
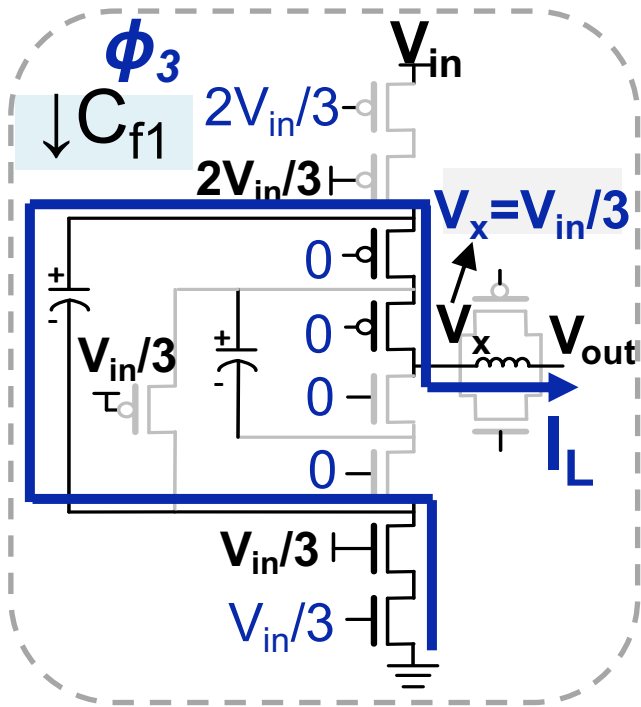
Converter Switching Cycle (7-phases)



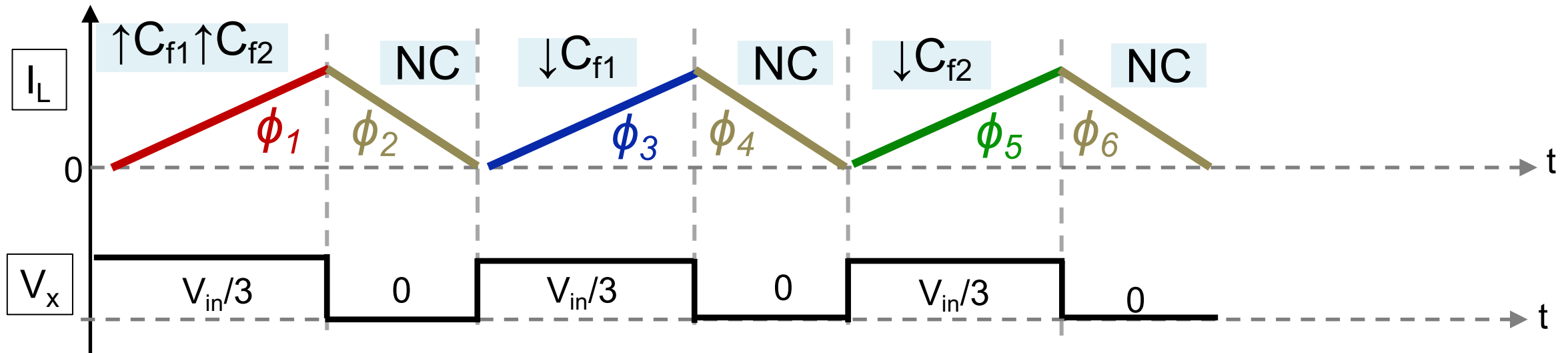
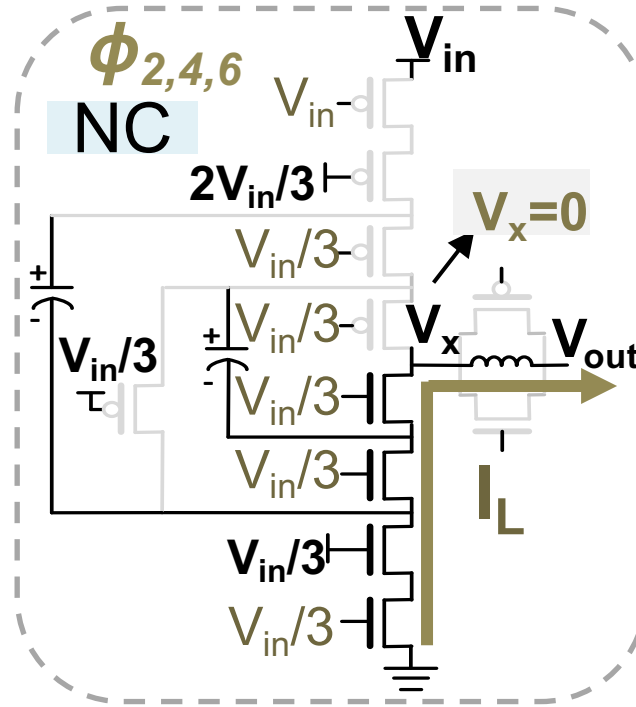
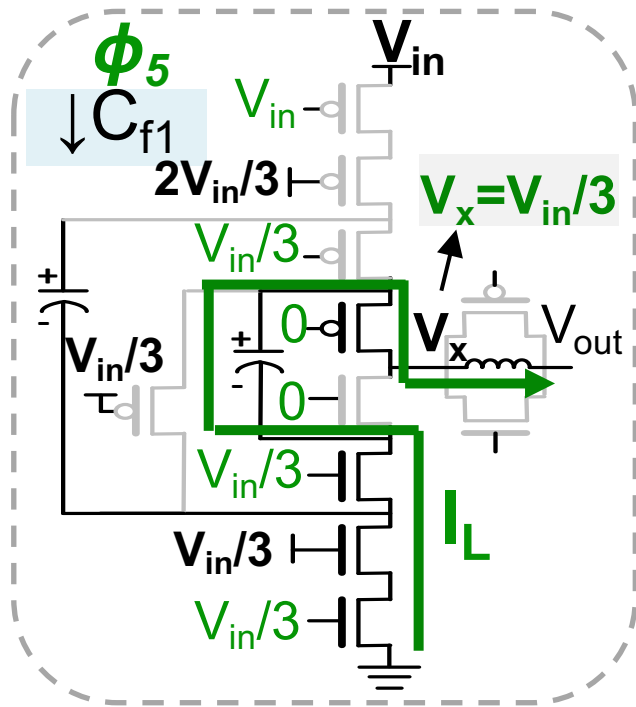
Converter Switching Cycle (7-phases)



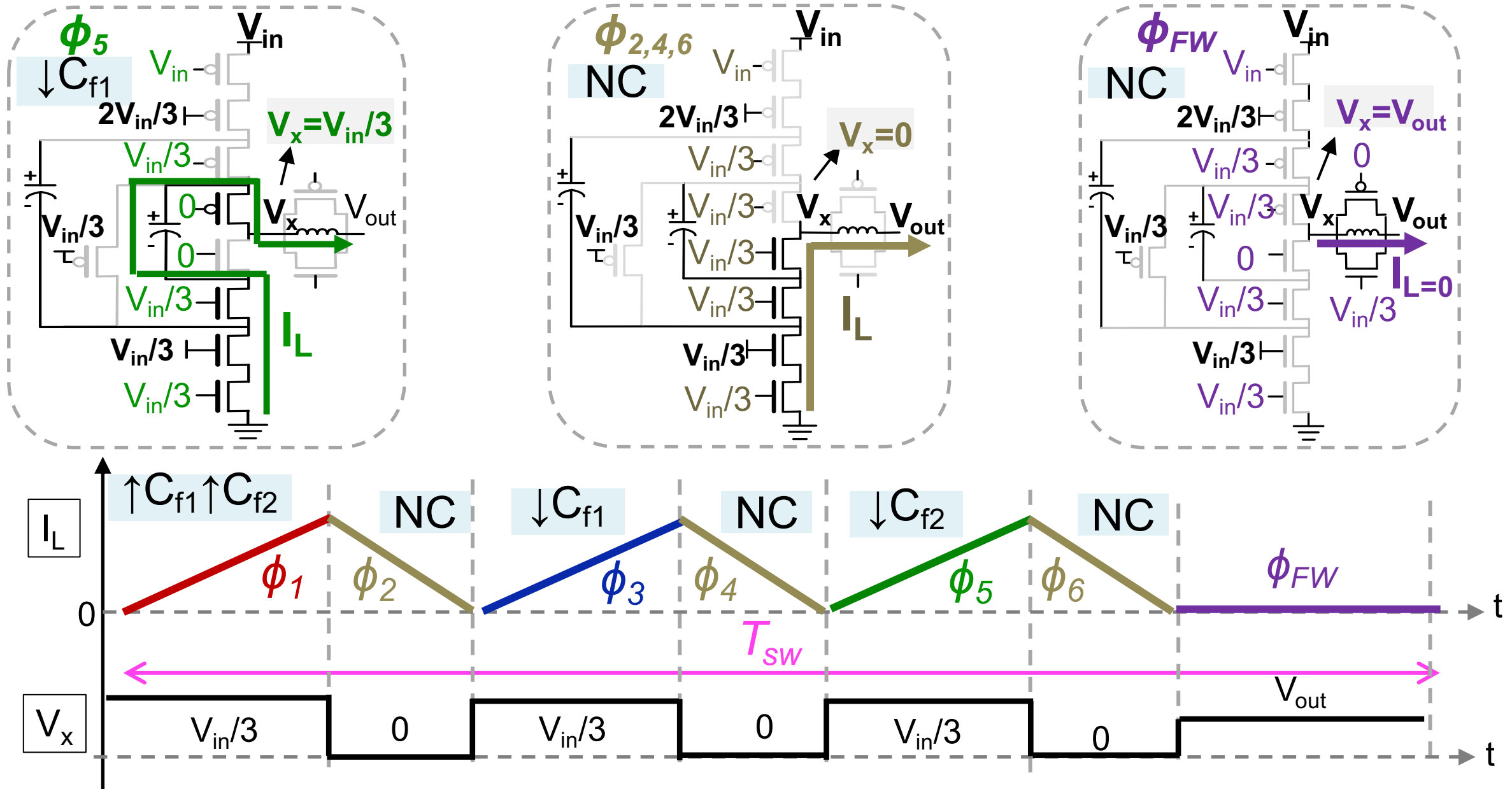
Converter Switching Cycle (7-phases)



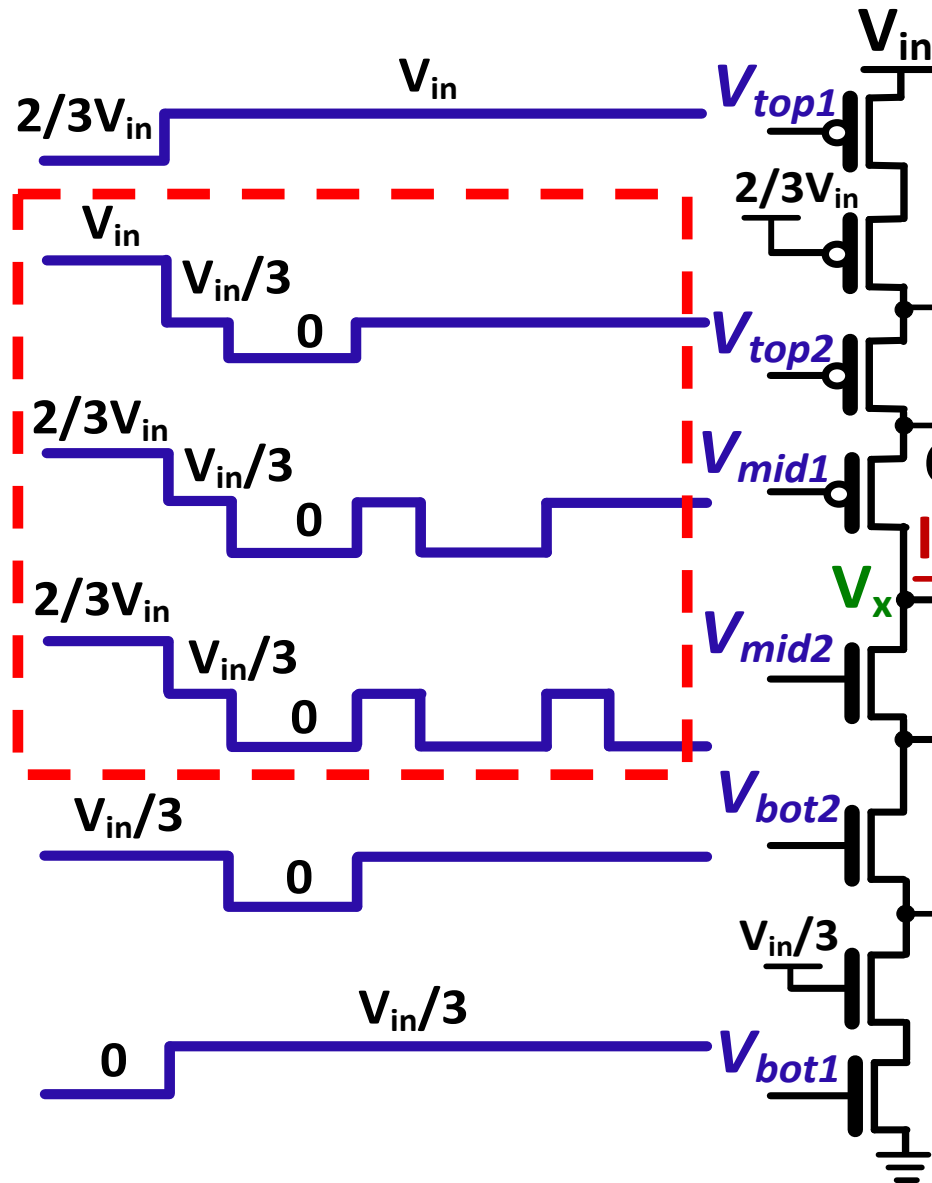
Converter Switching Cycle (7-phases)



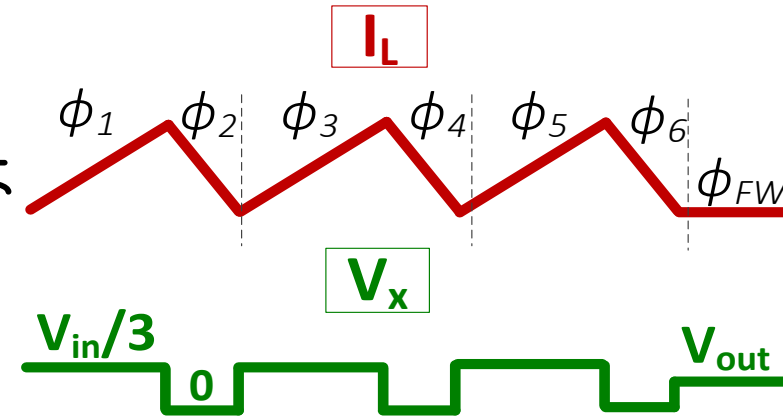
Converter Switching Cycle (7-phases)



Power Stage 3-Level Gate Signaling



3-Level gate signaling is required to ensure that none of the transistors exceed $V_{in}/3$



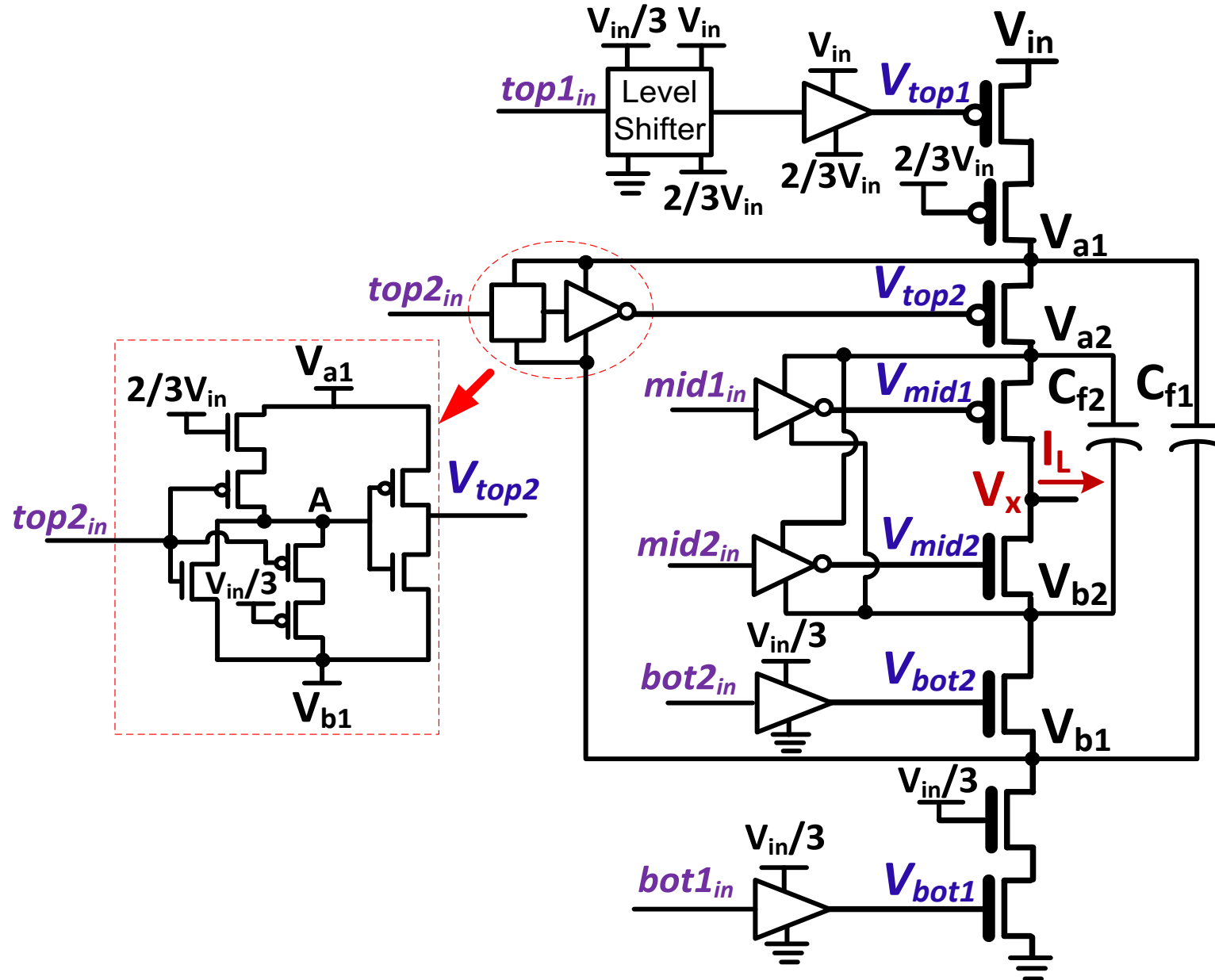
Challenge:

How to generate the 3-Level gate signals without complex stacked drivers and many level shifters?

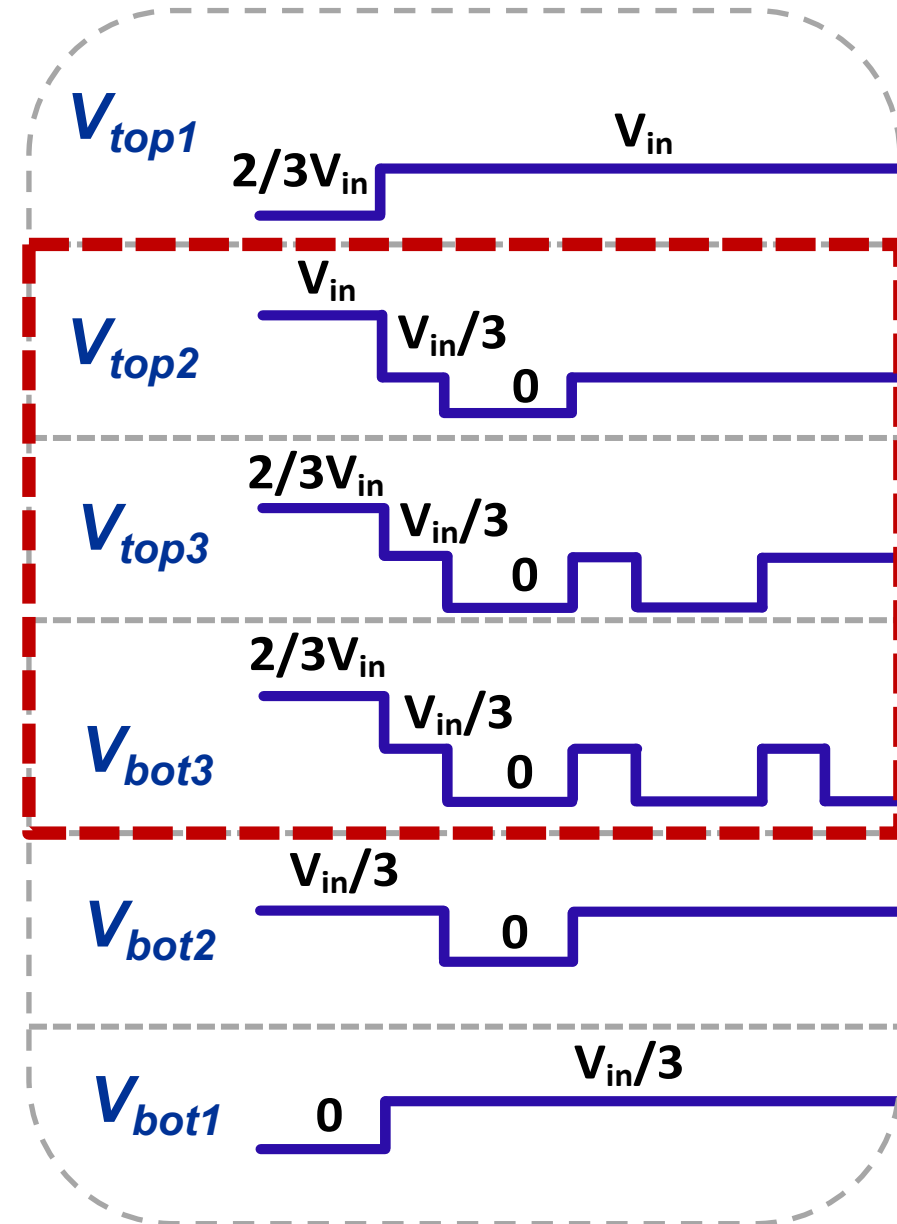
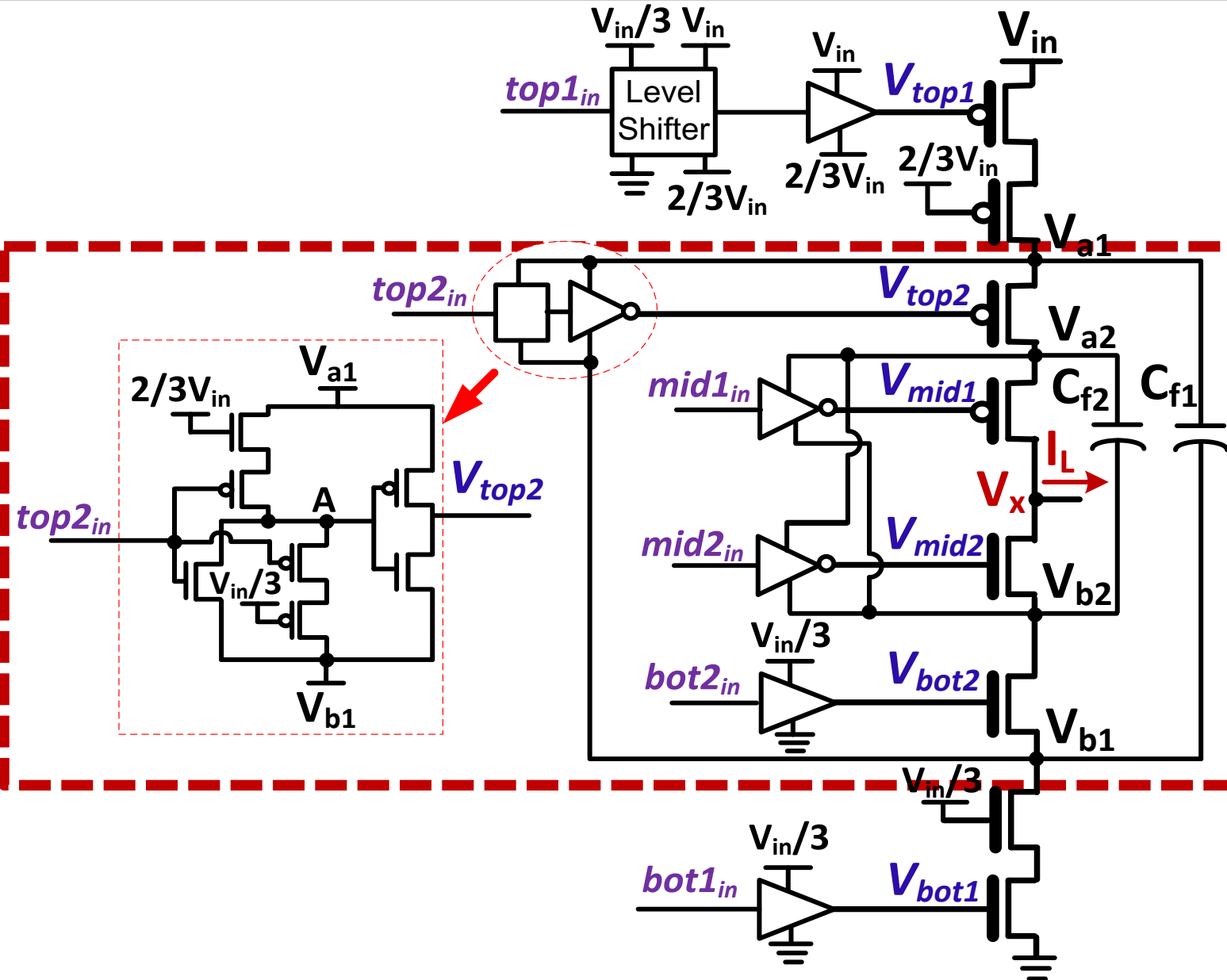
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- Proposed Hybrid Architecture
- Switching Phases of the Proposed Architecture
- **Circuit Details**
- Measurement Results
- Conclusion

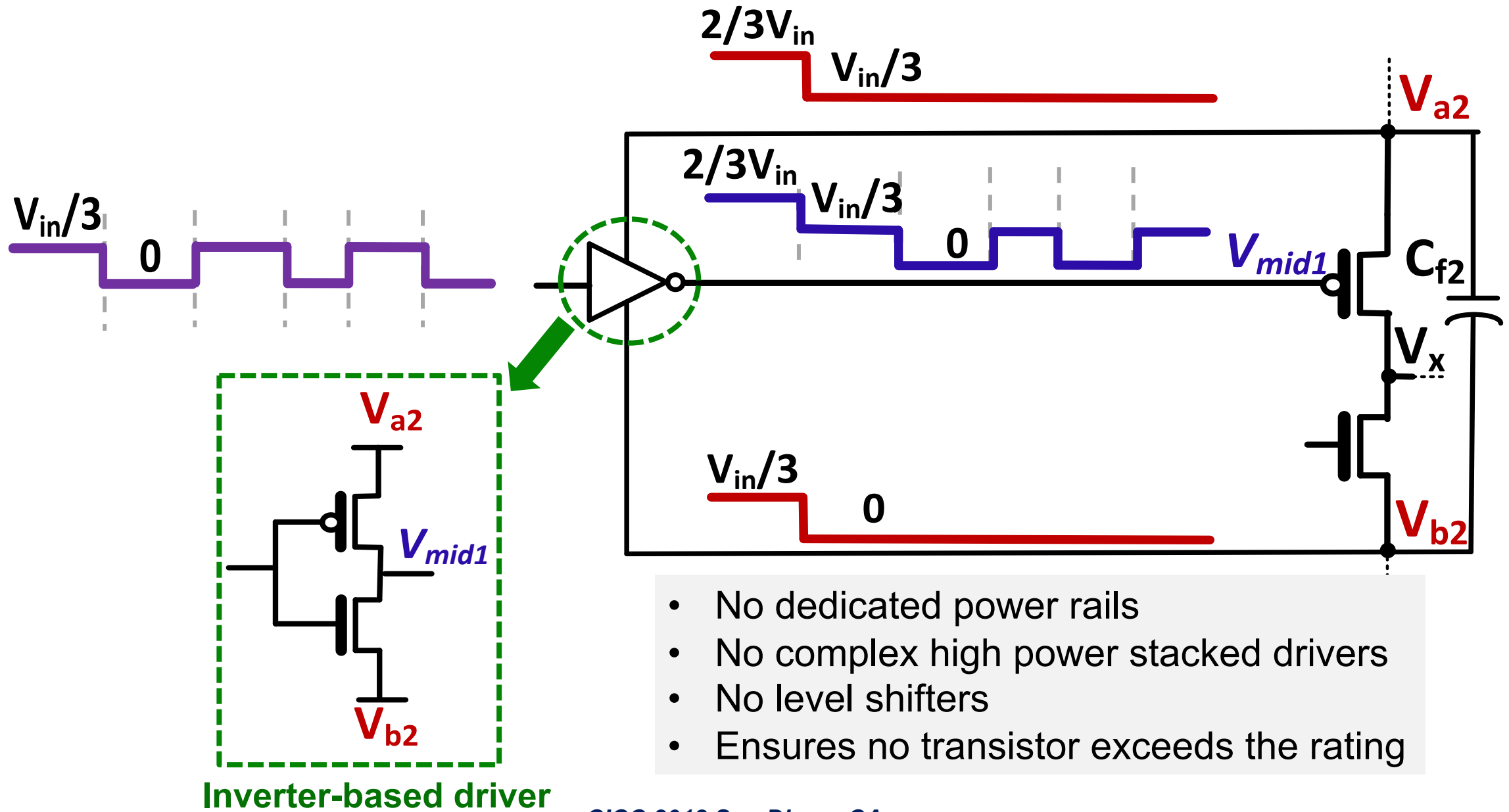
Driver Architecture



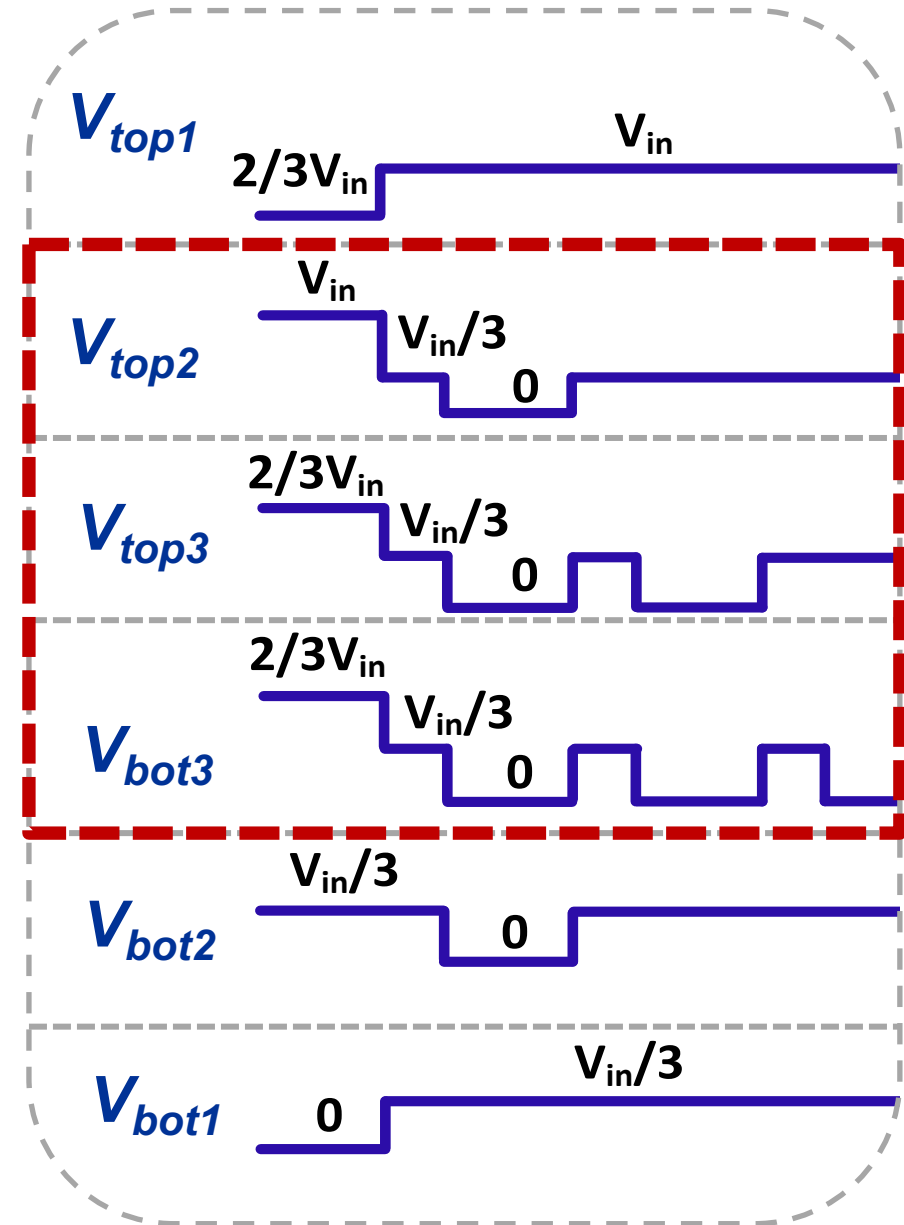
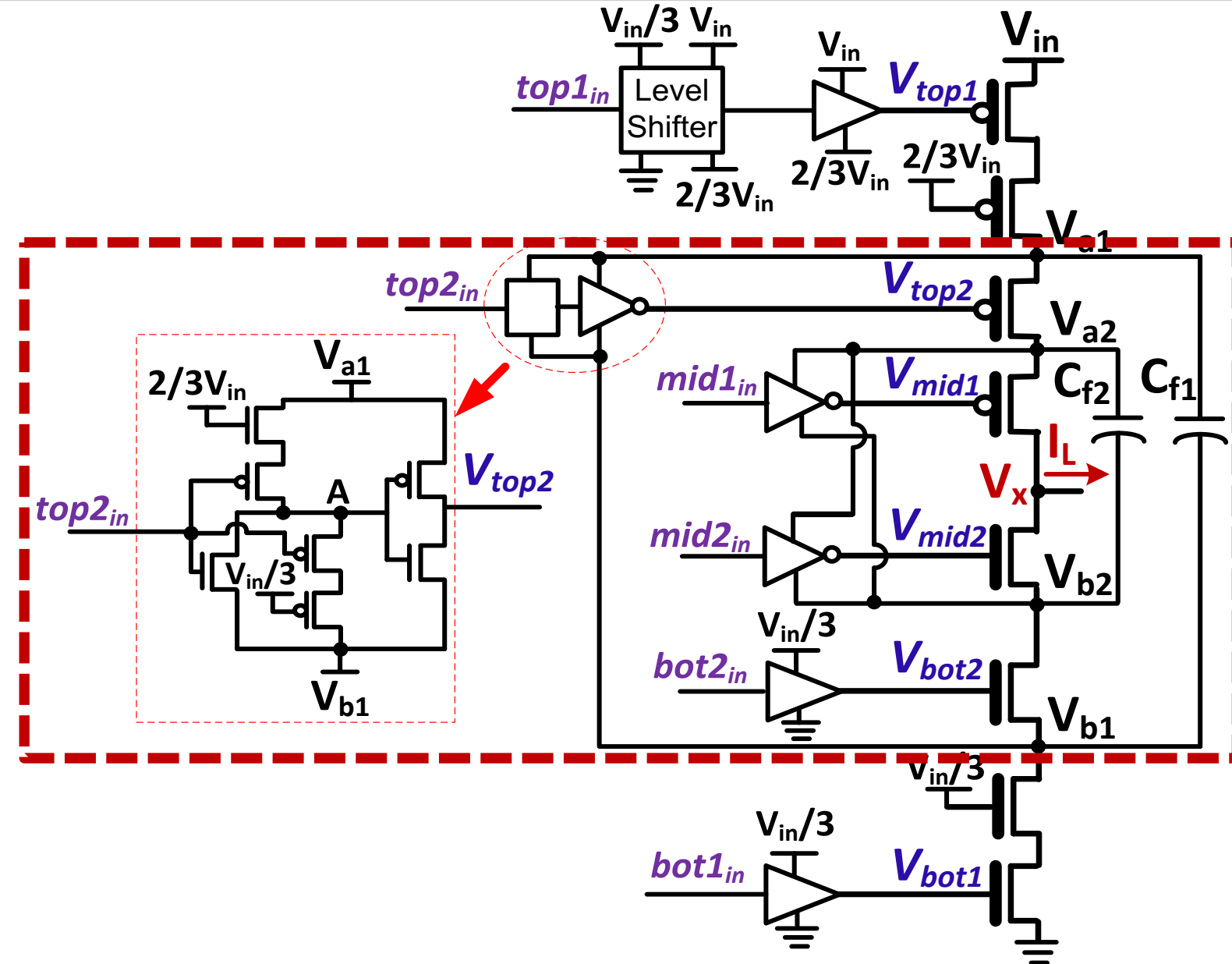
Driver Architecture



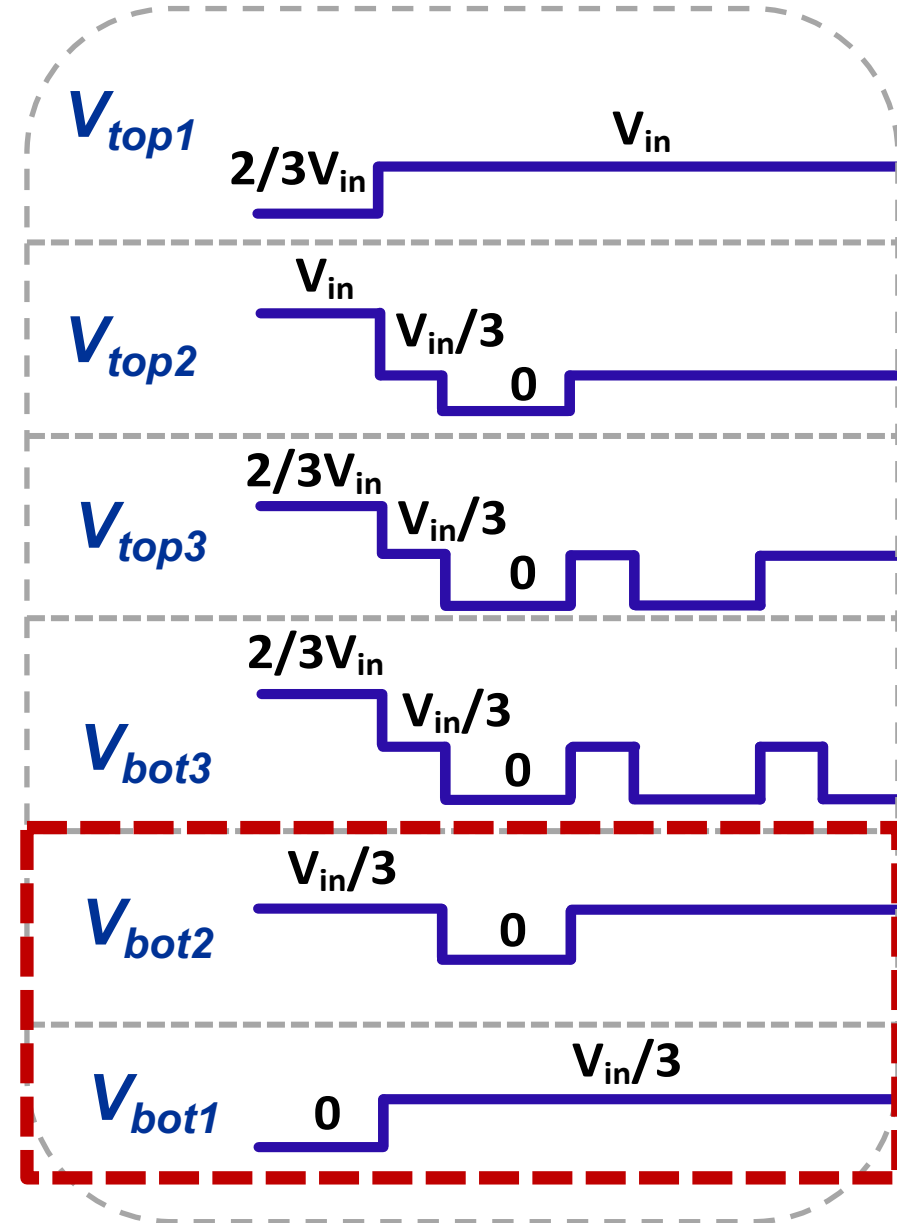
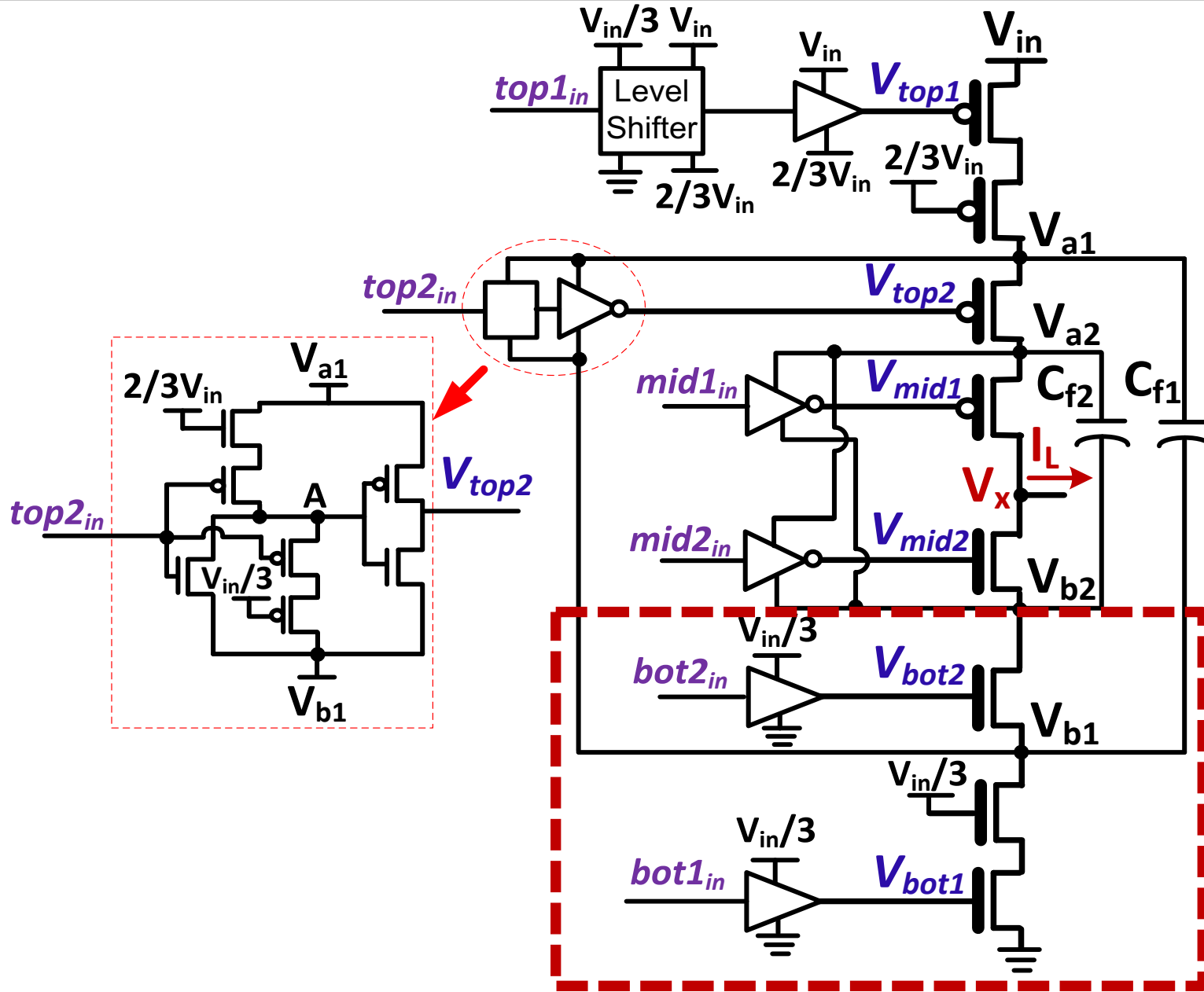
3-Level Gate Signaling Drivers



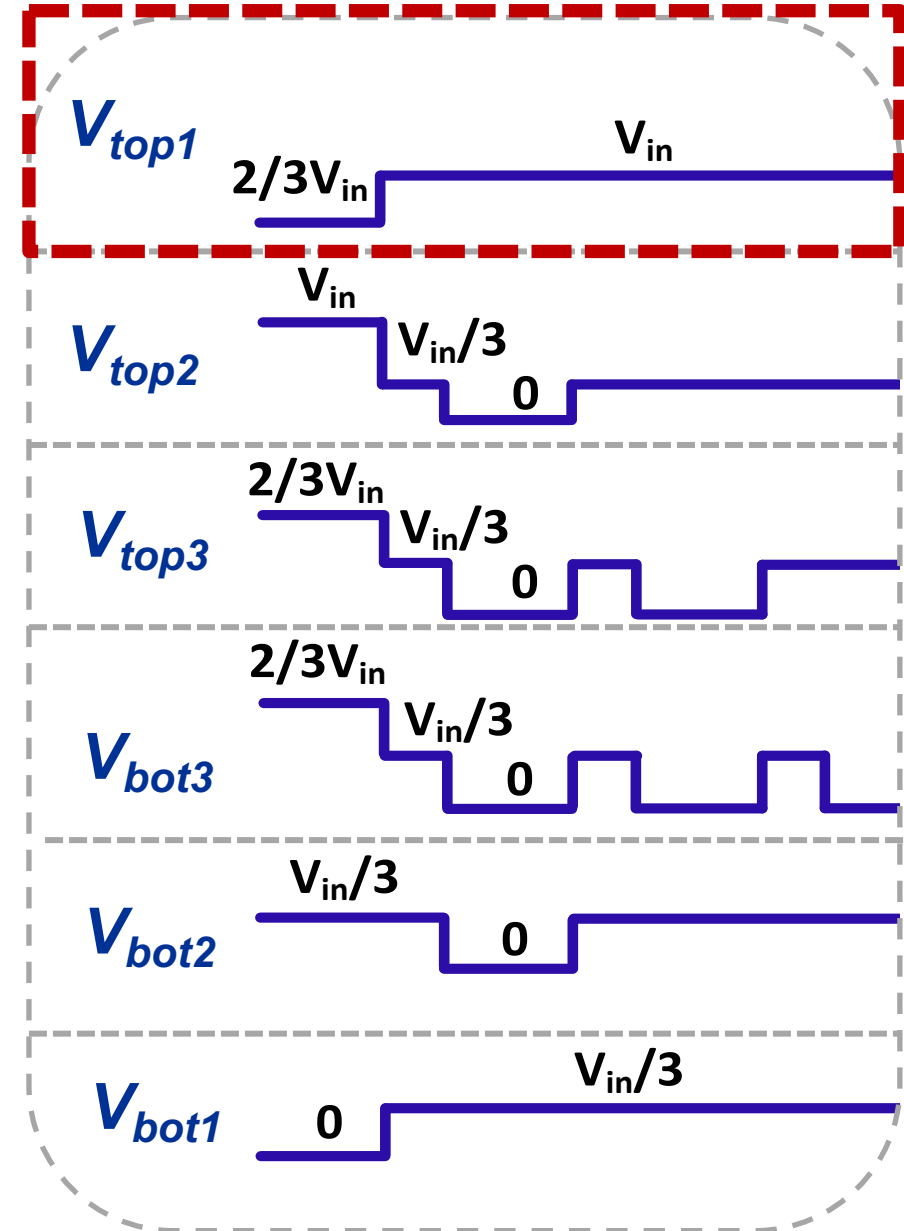
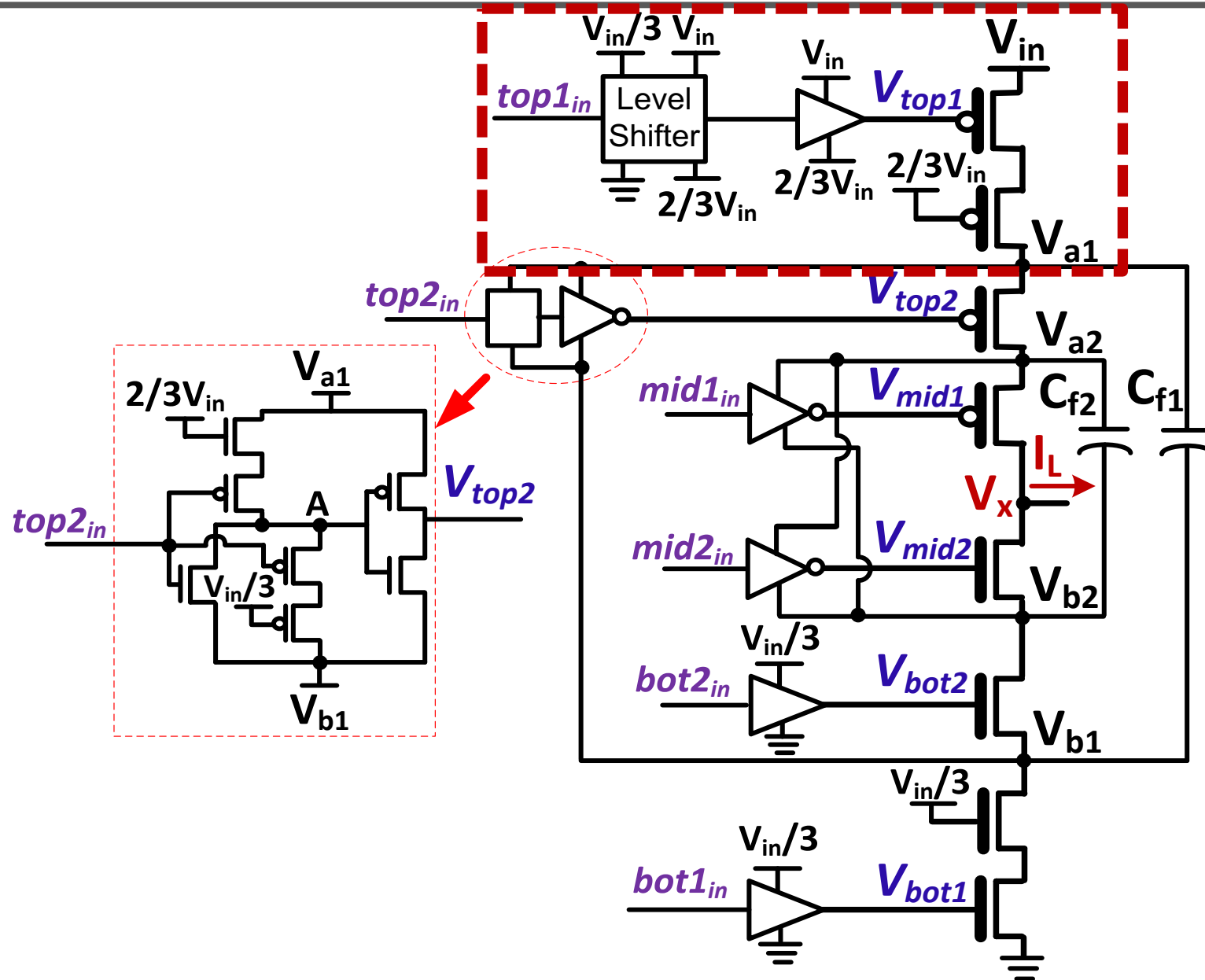
Driver Architecture



Driver Architecture



Driver Architecture

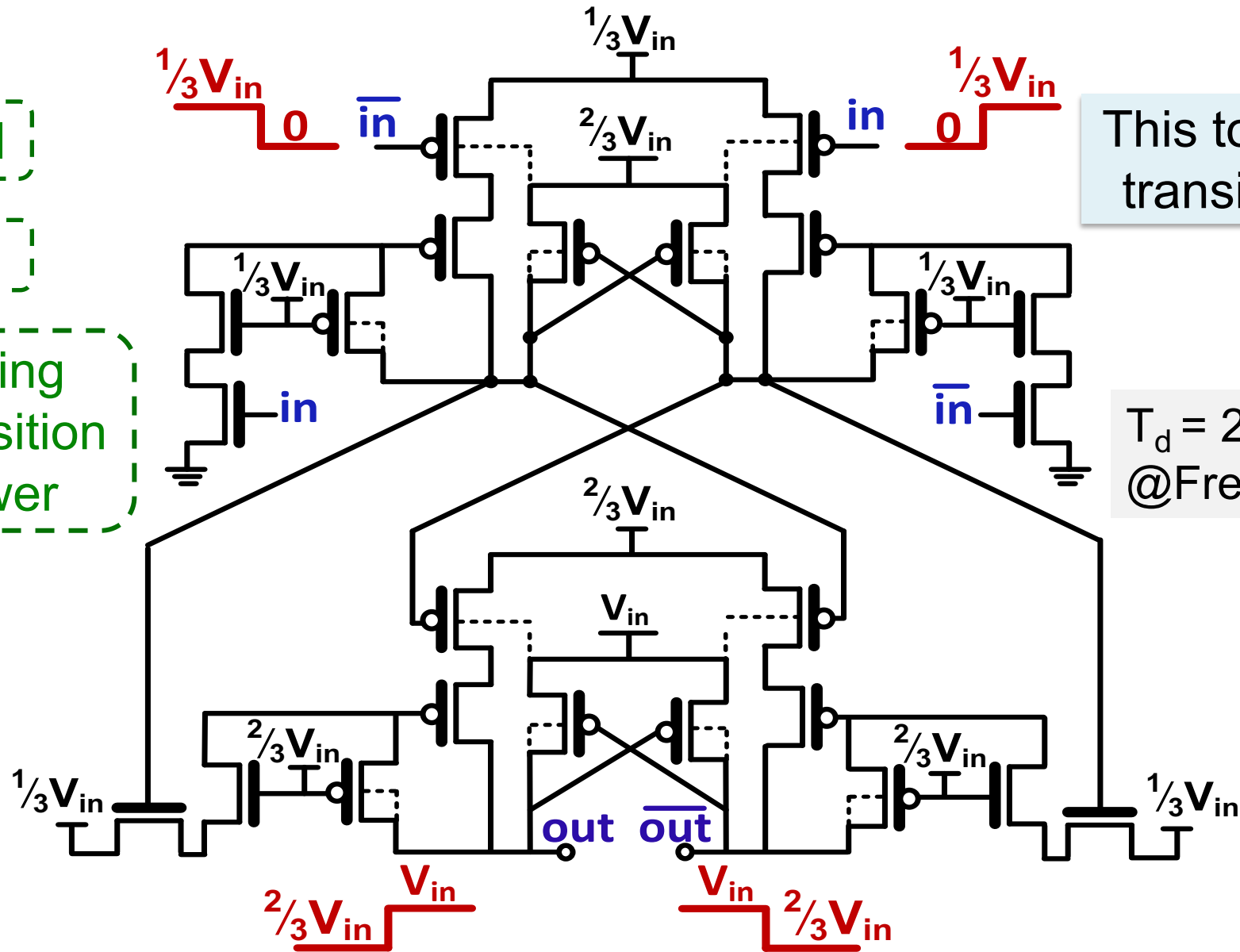


New Level-Shifter Topology ($0:V_{in}/3 \rightarrow 2V_{in}/3:V_{in}$)

All digital

No caps

Body biasing
for fast transition
& low power



This topology ensures no transistor exceeds $V_{in}/3$

$T_d = 230\text{ps}$ & $P = 1.27\text{nW}$
@Freq=1kHz & $V_{in} = 4.2\text{V}$

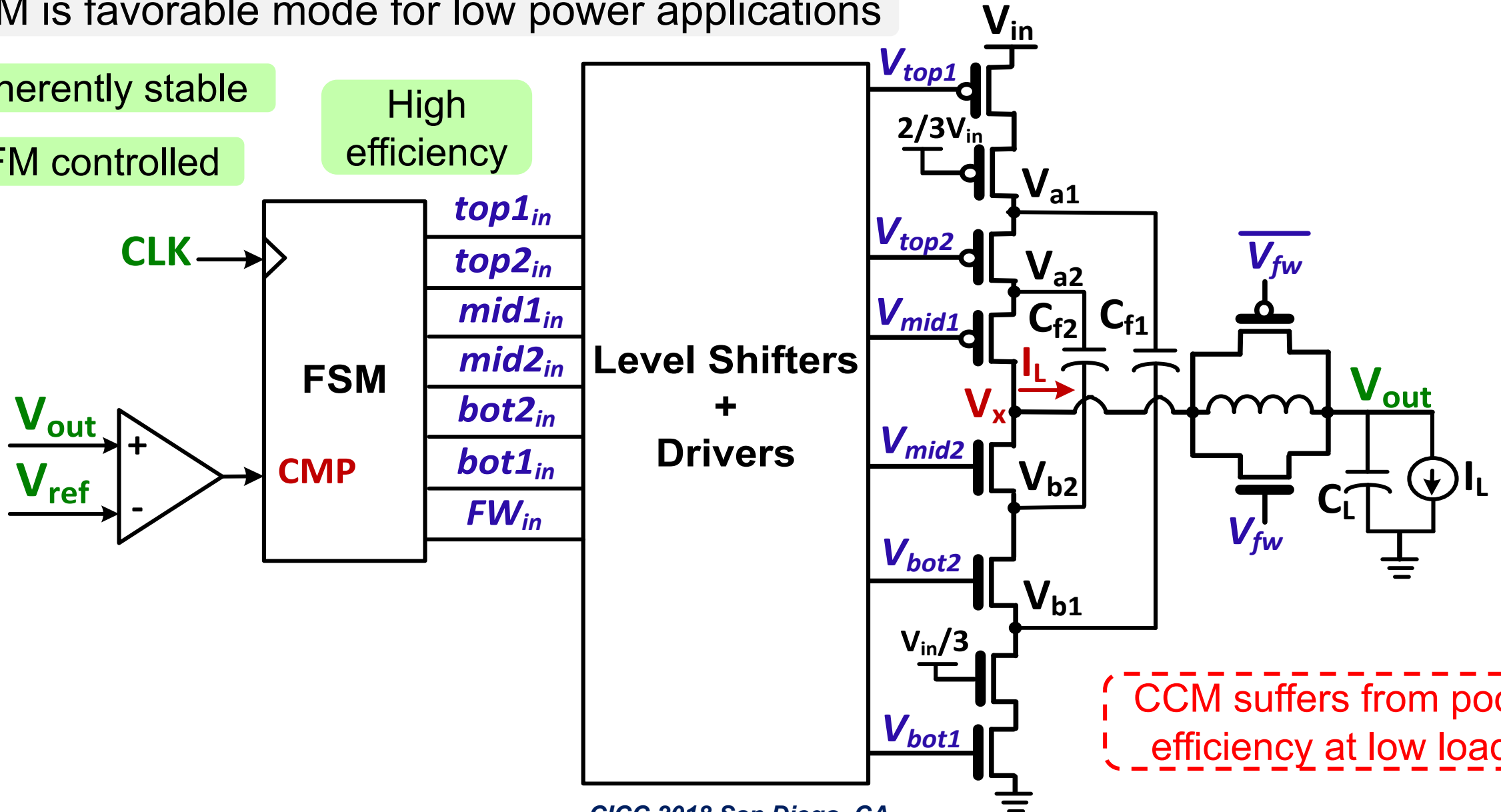
DCM-Operated Top-Level Architecture

DCM is favorable mode for low power applications

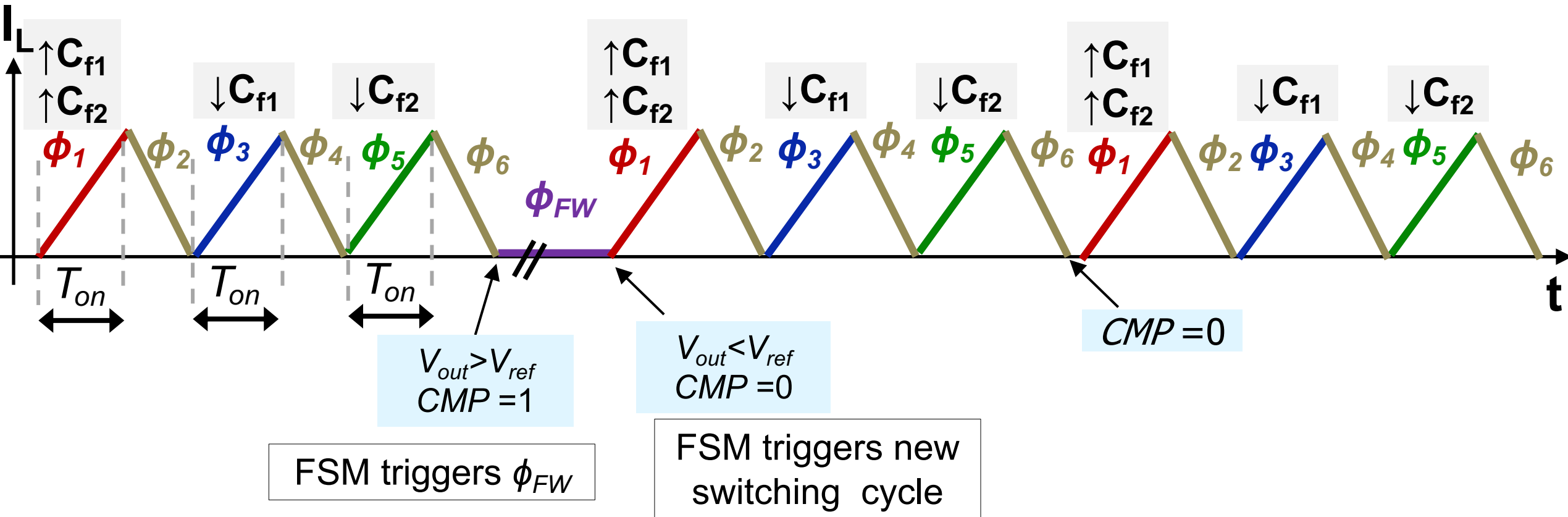
Inherently stable

PFM controlled

High efficiency



Constant On-Time PFM Control



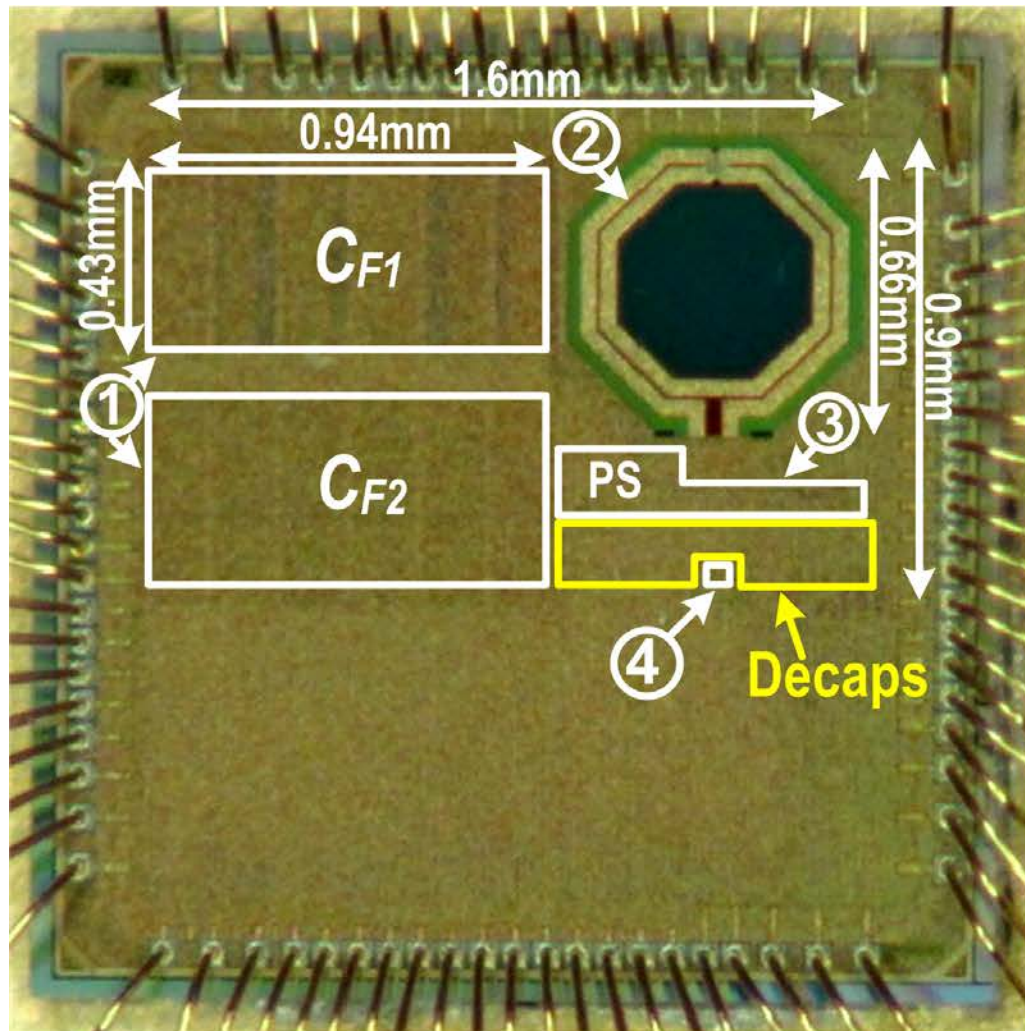
FSM checks the comparator output only at the end of ϕ_6

- Not to interrupt the flying cap charge balance
- Reduce F_{sw}

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Chip Microphotograph

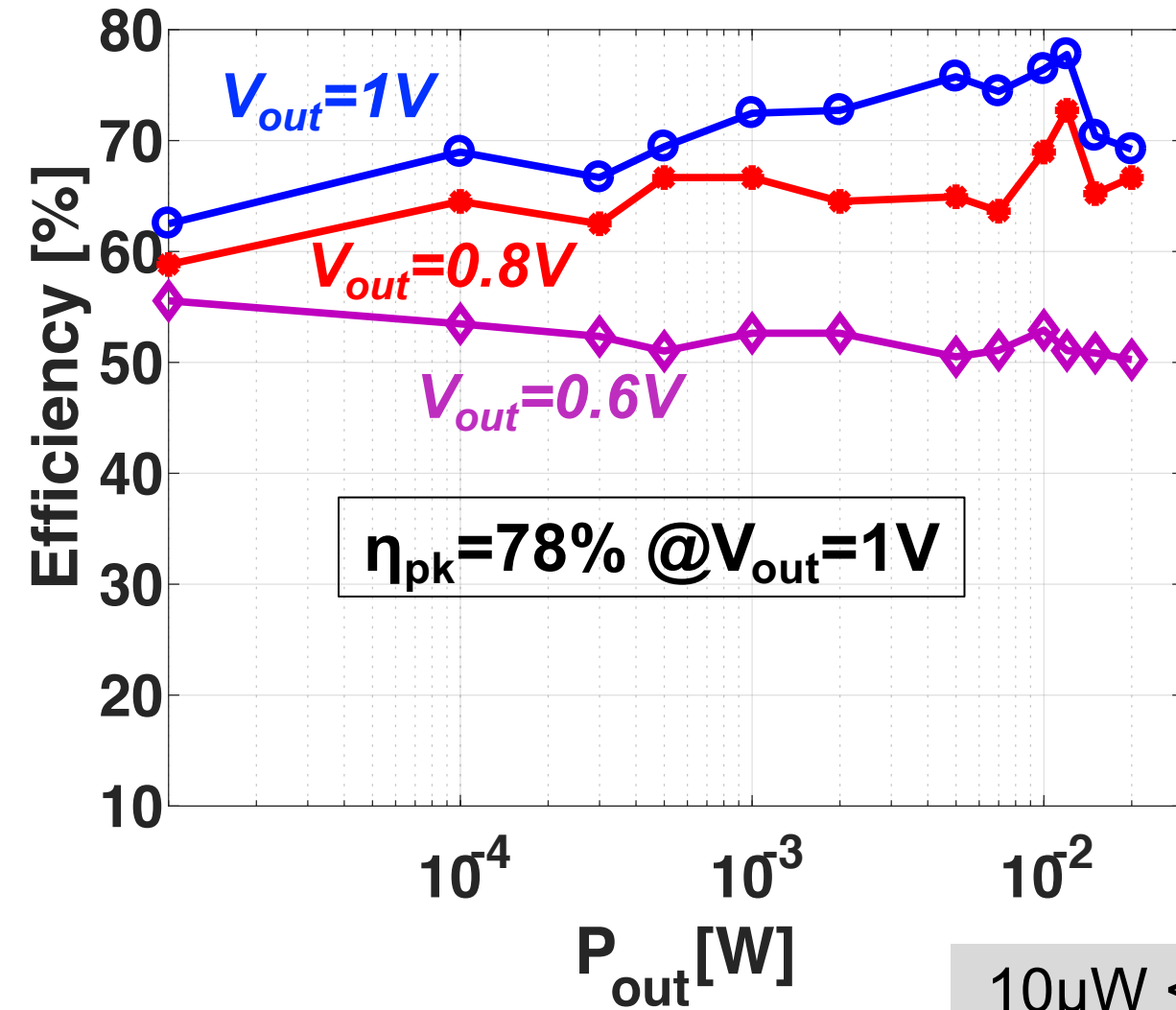


- ① Flying caps ($C_{f1}=C_{f2}=5nF$) [0.8084mm²]
- ② Inductor ($L=3nH$, $DCR=200m\Omega$) [0.4356mm²]
- ③ Power stage & drivers [0.06mm²]
- ④ Digital controller [0.000225mm²]

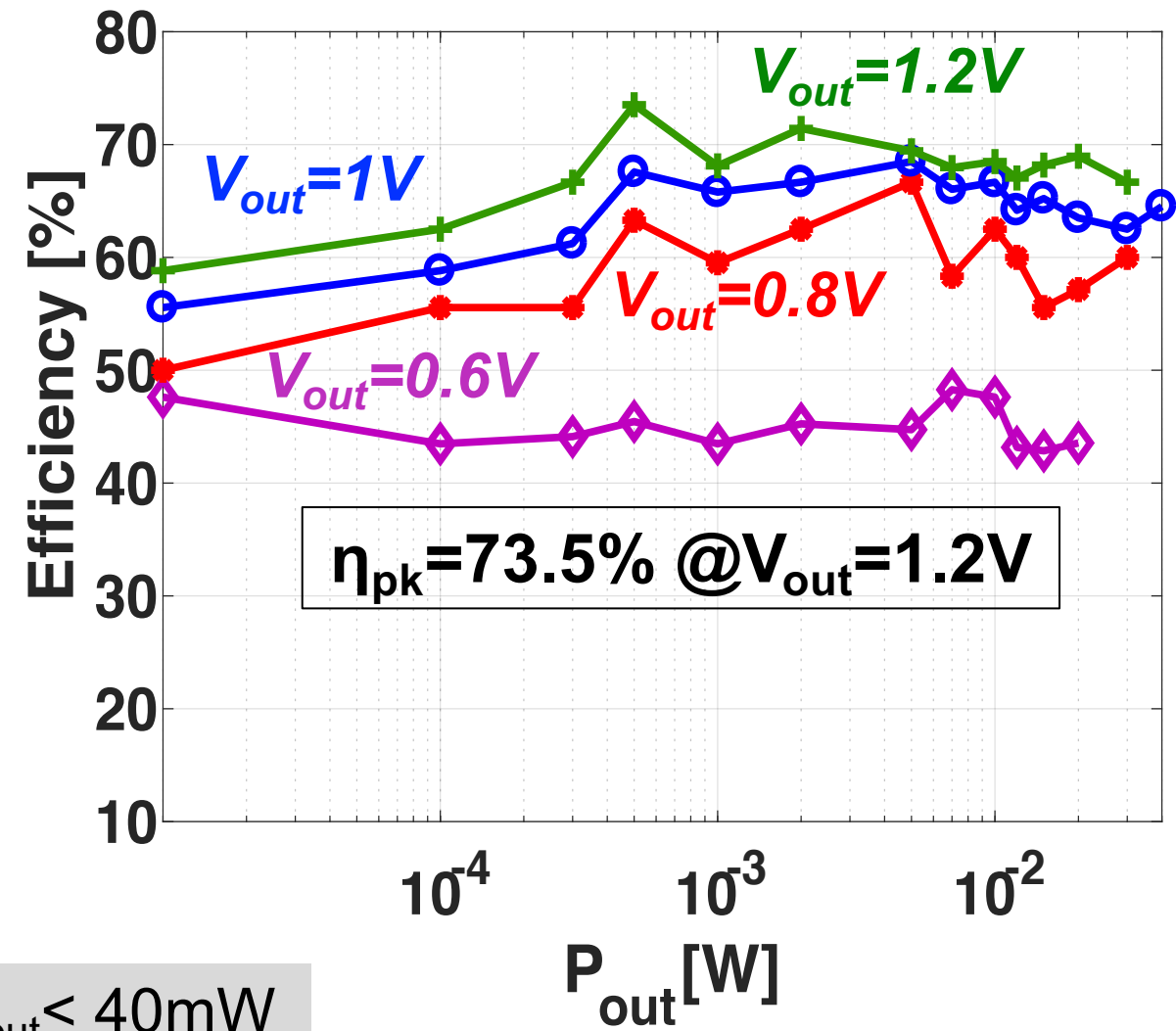
Implemented in 10-ML 28nm FDSOI
Total Area = 1.5mm²

Efficiency Measurement

$V_{in}=3.6V$



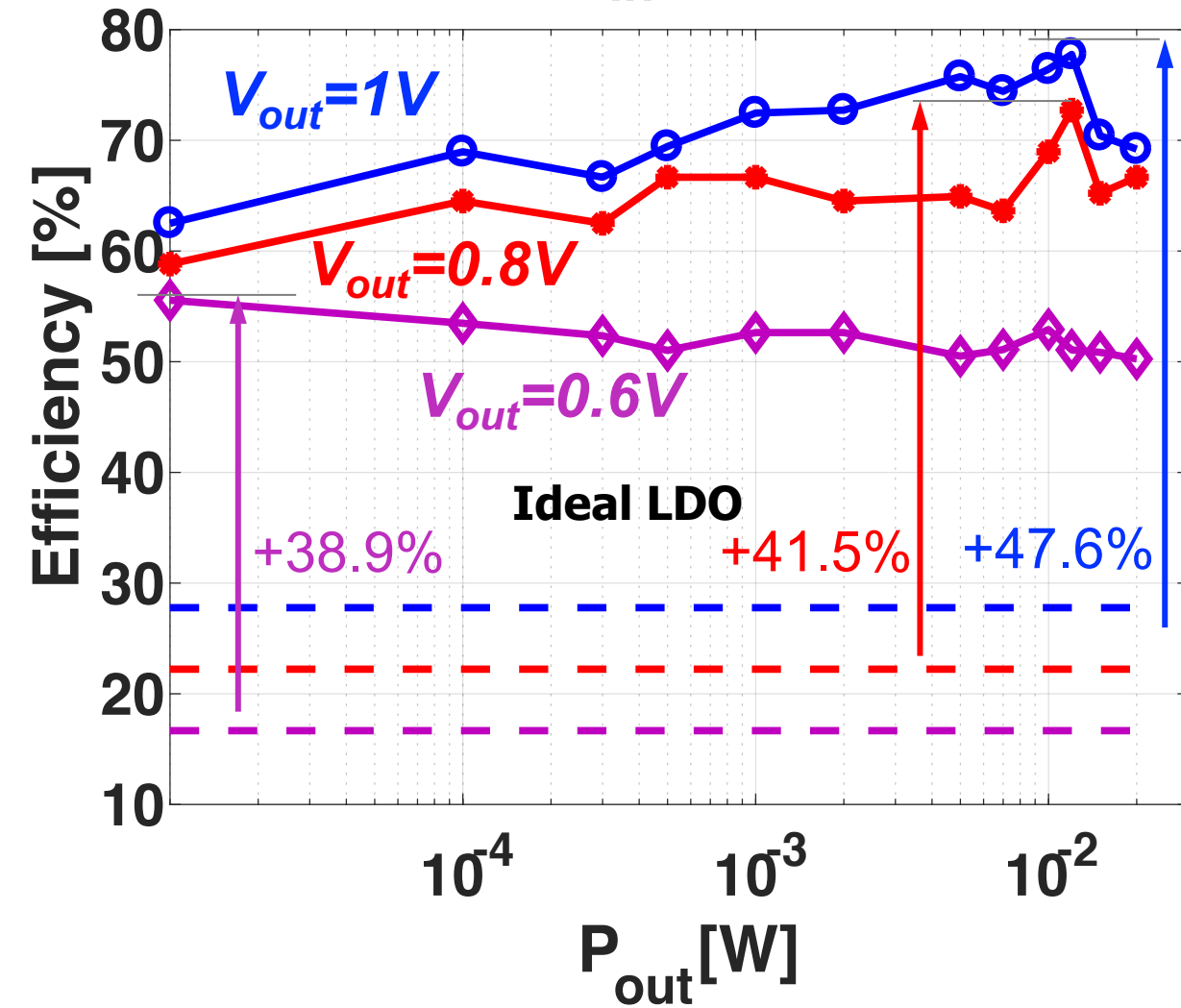
$V_{in}=4.2V$



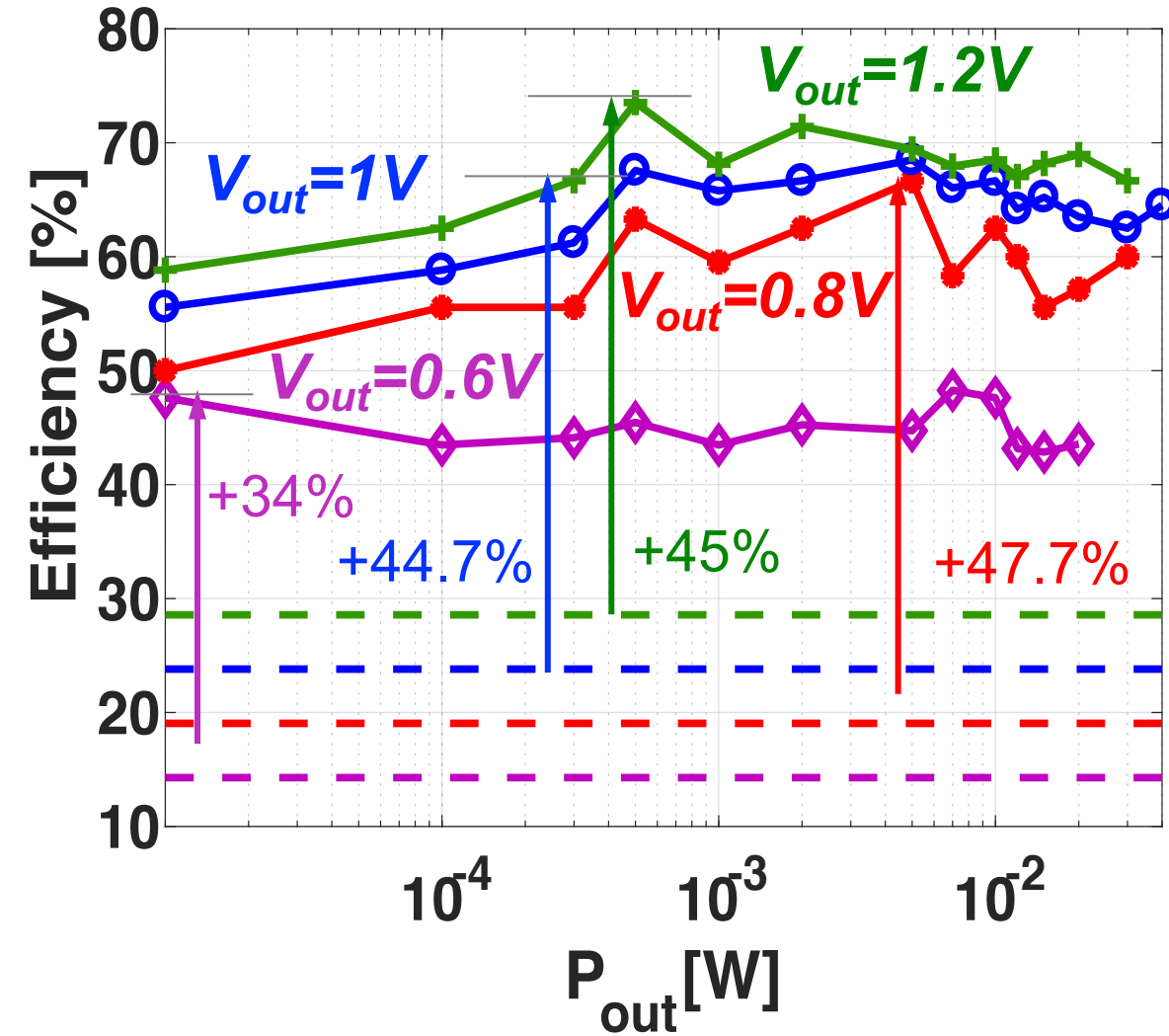
$10\mu W < P_{out} < 40mW$

Efficiency Measurement

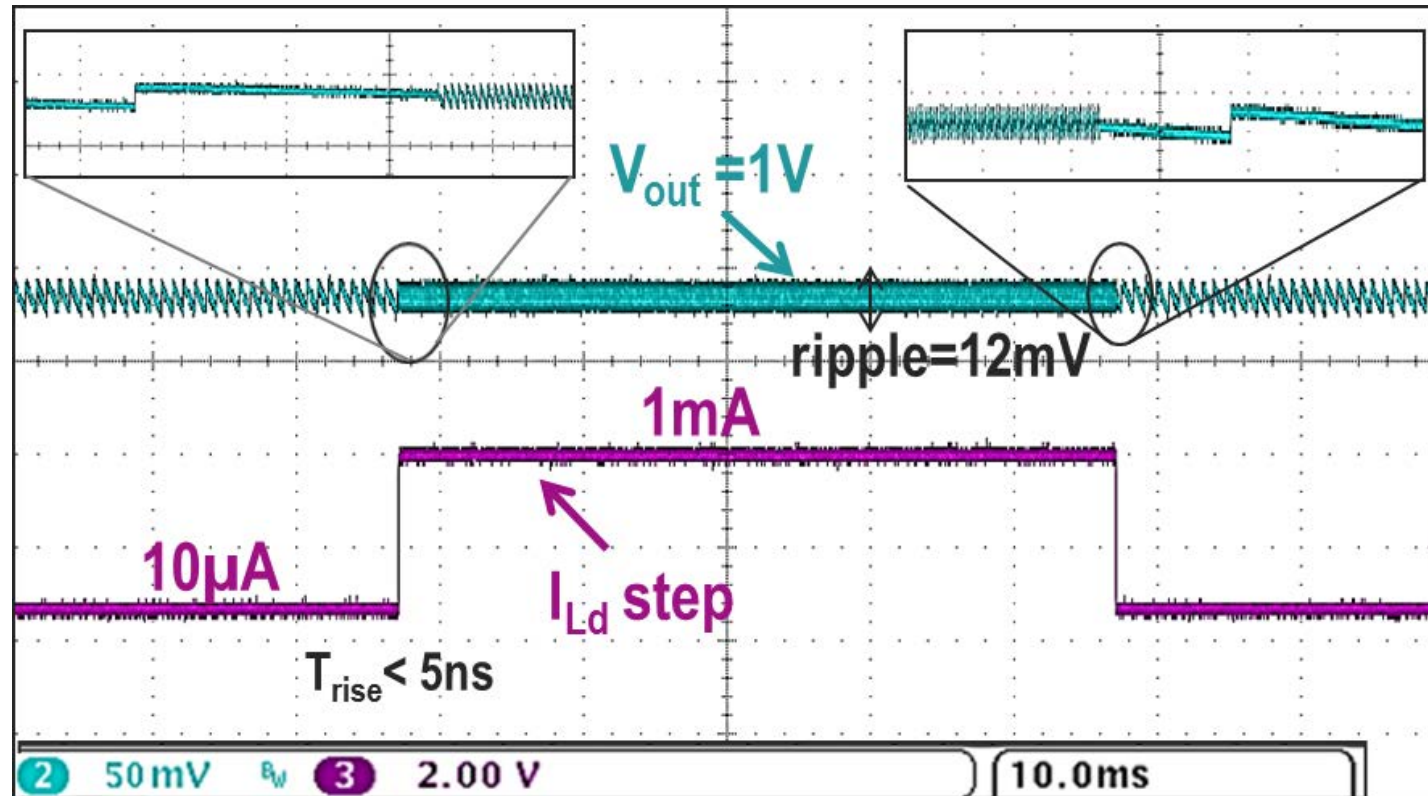
$V_{in}=3.6V$



$V_{in}=4.2V$



Measured Load Step Response



Load step ($10\mu\text{A} \rightarrow 1\text{mA}$) demonstrates:

- PFM control
- Negligible droop and output ripple=12mV

Comparison with Prior State-of-Art

	Breussegem, JSSC'11	Le, ISSCC'13	Bang, JSSC'16	Kim, JSSC'12	This Work
Technology	90nm	65nm	180nm	130nm	28nm FDSOI
Li-ion Capability	YES	YES	YES	NO	YES
Topology	SC	SC	SC	3-Level	4-Level
L (H) / No of phases	NA	NA	NA	4n / 4 phases	3n / 1 phase
CR	1/2	1/3, 2/5	117 CRs	NA	NA
V _{in} (V)	3-3.9	3-4	3.4-4.3	2.4	2.8 - 4.5
V _{out} (V)	1.3@V _{in} =3 1.42@V _{in} =3.3 1.5@V _{in} =3.6	1	0.45-1.5	0.4-1.4	0.6-1.2
F _{max} (MHz)	70	300	2.7	200	200
P _{out} (mW)	1*-150	6*-162	0.001*-0.45	120*-1000	0.01-40
Dynamic Range (P _{max} /P _{min})	150	27	450	8.3	4,000
Area (mm ²)	3.6*	0.64	1.69	5	1.5
Overall peak efficiency @1/CR	77.3%@2.3	74.3%@3.6	72%@2.6	77%@2.2*	78%@3.6
Maximum improvement over LDO@ (1/CR) _{range}	33.9%* @2.3	35-45%* @3-4	21%-49.5%* @3-7	18-31%* @2-4	34-50.5% @3-7

Comparison with Prior State-of-Art

	Breussegem, JSSC'11	Le, ISSCC'13	Bang, JSSC'16	Kim, JSSC'12	This Work
Technology	90nm	65nm	180nm	130nm	28nm FDSOI
Li-ion Capability	YES	YES	YES	NO	YES
Topology	SC	SC	SC	3-Level	4-Level
L (H) No of phases	NA	NA	NA	4n 4 phases	3n 1 phase
CR	1/2	1/3, 2/5	117 CRs	NA	NA
V_{in} (V)	3-3.9	3-4	3.4-4.3	2.4	2.8 - 4.5
V_{out} (V)	1.3@ $V_{in}=3$ 1.42@ $V_{in}=3.3$ 1.5@ $V_{in}=3.6$	1	0.45-1.5	0.4-1.4	0.6-1.2
F_{max} (MHz)	70	300	2.7	200	200
P_{out} (mW)	1*-150	6*-162	0.001*-0.45	120*-1000	0.01-40
Dynamic Range (P_{max}/P_{min})	150	27	450	8.3	4,000
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Maximum improvement over LDO@ (1/CR) _{range}	33.9%* @2.3	35-45%* @3-4	21%-49.5%* @3-7	18-31%* @2-4	34-50.5% @3-7

Comparison with Prior State-of-Art

	Breussegem, JSSC'11	Le, ISSCC'13	Bang, JSSC'16	Kim, JSSC'12	This Work
Technology	90nm	65nm	180nm	130nm	28nm FDSOI
Li-ion Capability	YES	YES	YES	NO	YES
Topology	SC	SC	SC	3-Level	4-Level
L (H) No of phases	NA	NA	NA	4n 4 phases	3n 1 phase
CR	1/2	1/3, 2/5	117 CRs	NA	NA
V_{in} (V)	3-3.9	3-4	3.4-4.3	2.4	2.8 - 4.5
V_{out} (V)	1.3@ $V_{in}=3$ 1.42@ $V_{in}=3.3$ 1.5@ $V_{in}=3.6$	1	0.45-1.5	0.4-1.4	0.6-1.2
F_{max} (MHz)	70	300	2.7	200	200
P_{out} (mW)	1*-150	6*-162	0.001*-0.45	120*-1000	0.01-40
Dynamic Range (P_{max}/P_{min})	150	27	450	8.3	4,000
Area (mm ²)	3.6*	0.64	1.69	5	1.5
Overall peak efficiency @1/CR	77.3%@2.3	74.3%@3.6	72%@2.6	77%@2.2*	78%@3.6
Maximum improvement over LDO@ (1/CR) _{range}	33.9%* @2.3	35-45%* @3-4	21%-49.5%* @3-7	18-31%* @2-4	34-50.5% @3-7

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PFM control

$$F_{sw-out} \leq 200\text{MHz}$$

$$1\text{kHz} \leq F_{sw-in} \leq 67\text{MHz}$$

Comparison with Prior State-of-Art

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Outline

- Prior Work
- Proposed Hybrid Architecture
- Switching Phases of the Proposed Architecture
- Circuit Details
- Measurement Results
- Conclusion

Conclusion

- This work demonstrated that integrating a DC-DC converter compatible with Li-ion battery voltage (2.8-4.2V), using low-voltage transistors (1.5V) in scaled CMOS is feasible.
- A modified 4-level topology was proposed to reduce the cap area by 4x
- The proposed architecture is DCM-operated to achieve high efficiency at a low load range appropriate for IoT applications (10 μ W-40mW)
- The proposed converter achieved a peak efficiency of 78% and 34%-50.5% efficiency improvement over an ideal LDO

The authors thank ST Microelectronics for chip fabrication